

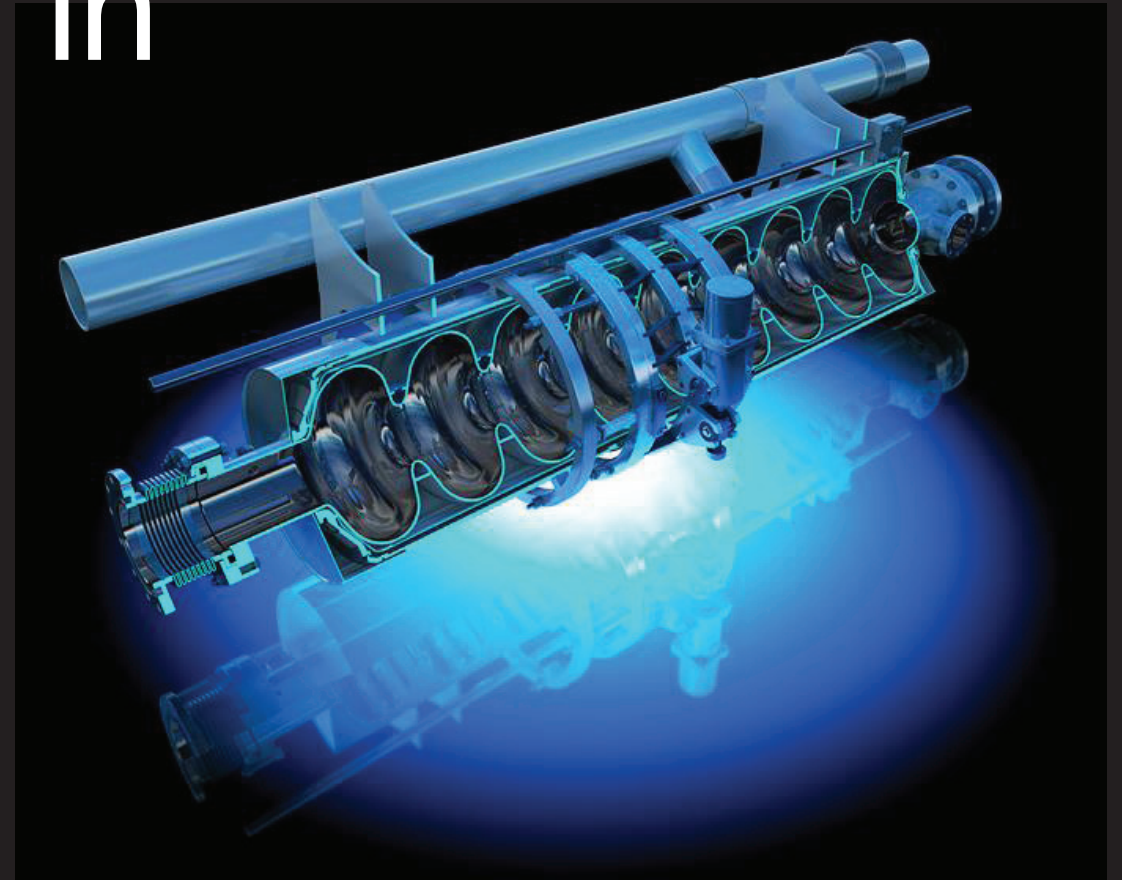
Transition Edge Sensors for quench localization in SRF cavity testing

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Zsolt Ferenc Kovács, Tobias Stegmaier

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Presentation of our team



Giovanna
Vandoni

- BE-RF
- Senior Scientist
- SRF activities coordinator



Torsten Koettig

- TE-CRG-CI
- Senior Cryogenics Scientist
- Cryolab R&D Coordinator



Hernán Furci

- BE-RF-SRF
- Senior Fellow
- Cryogenics Scientist
- R&D project responsible



Tobias
Stegmaier

- BE-RF-SRF
- Technical Student
- Masters thesis on Cryogenic experimental techniques for SRF



Zsolt Kovács

- BE-RF-SRF
- Technical Student
- Finished his bachelor in Material Science with thesis in development of TES films

Mentors

Project started in March 2016

Quench localization techniques

Quench localization

Future accelerators

- Need of testing superconducting cavities of variable size and geometry.

QUENCH: limits performance

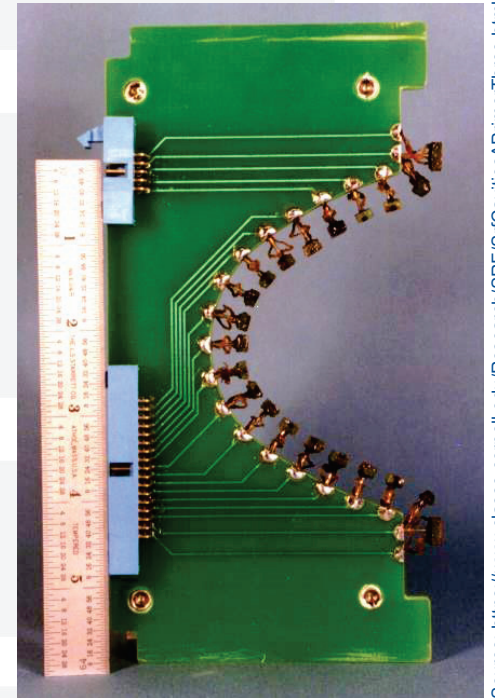
- Where did the quench start?
- Localized? Magnetic?
- What kind of defect induced the quench?
- Can the problem be corrected?

Contact thermometry

- Placing temperature sensors on the cavity walls
- Requires individual preparation of each cavity

Non- contact thermometry

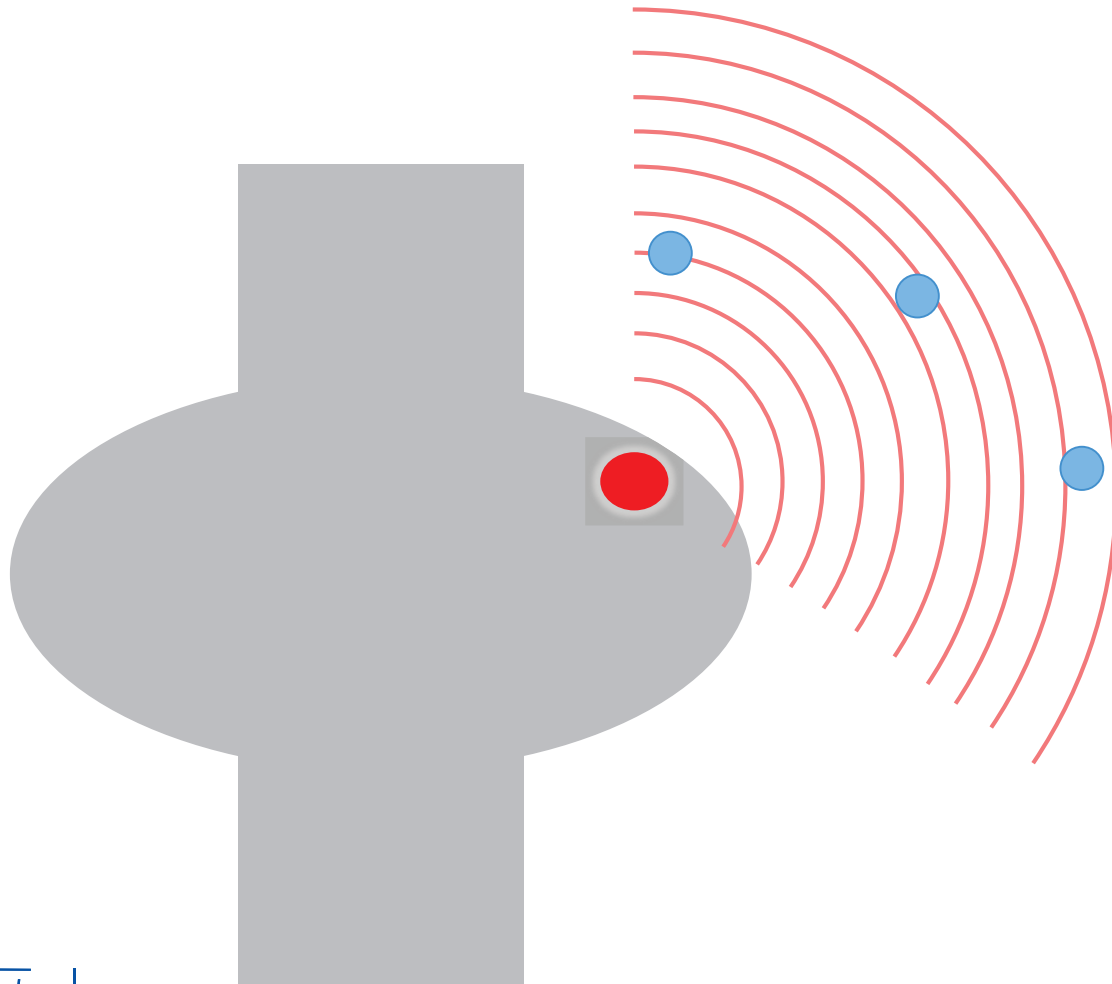
- Allows systematic and versatile testing of diverse cavities
- Technique based on superfluid helium second sound



Source: <https://www.classe.cornell.edu/Research/SRF/SrfCavities/APrimerThree.html>

Non-contact thermal mapping

(for **He-II** cooled cavities)



One of He-II many outstanding properties is **second sound: temperature-entropy wave**

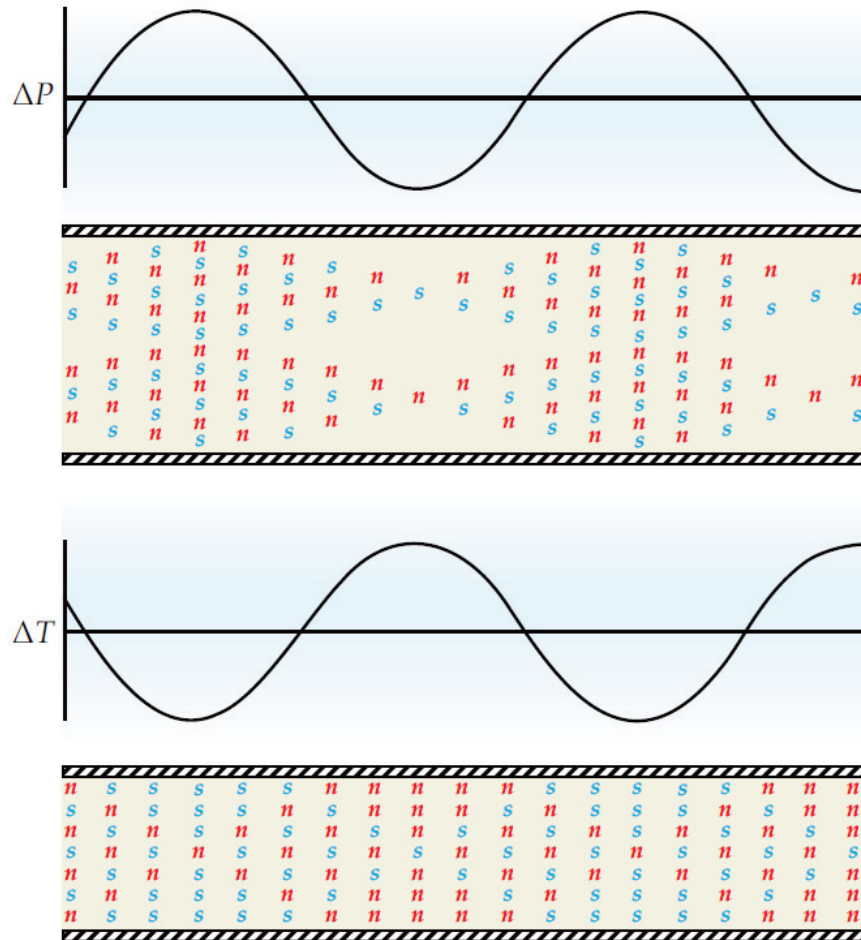
This wave is originated by a **transient heat flux** on a wall in contact with the fluid.

A quenching surface produces **second sound!!!**

Measuring the difference in time of flight to many sensors, the origin of the wave can be trilaterated (GPS-like).

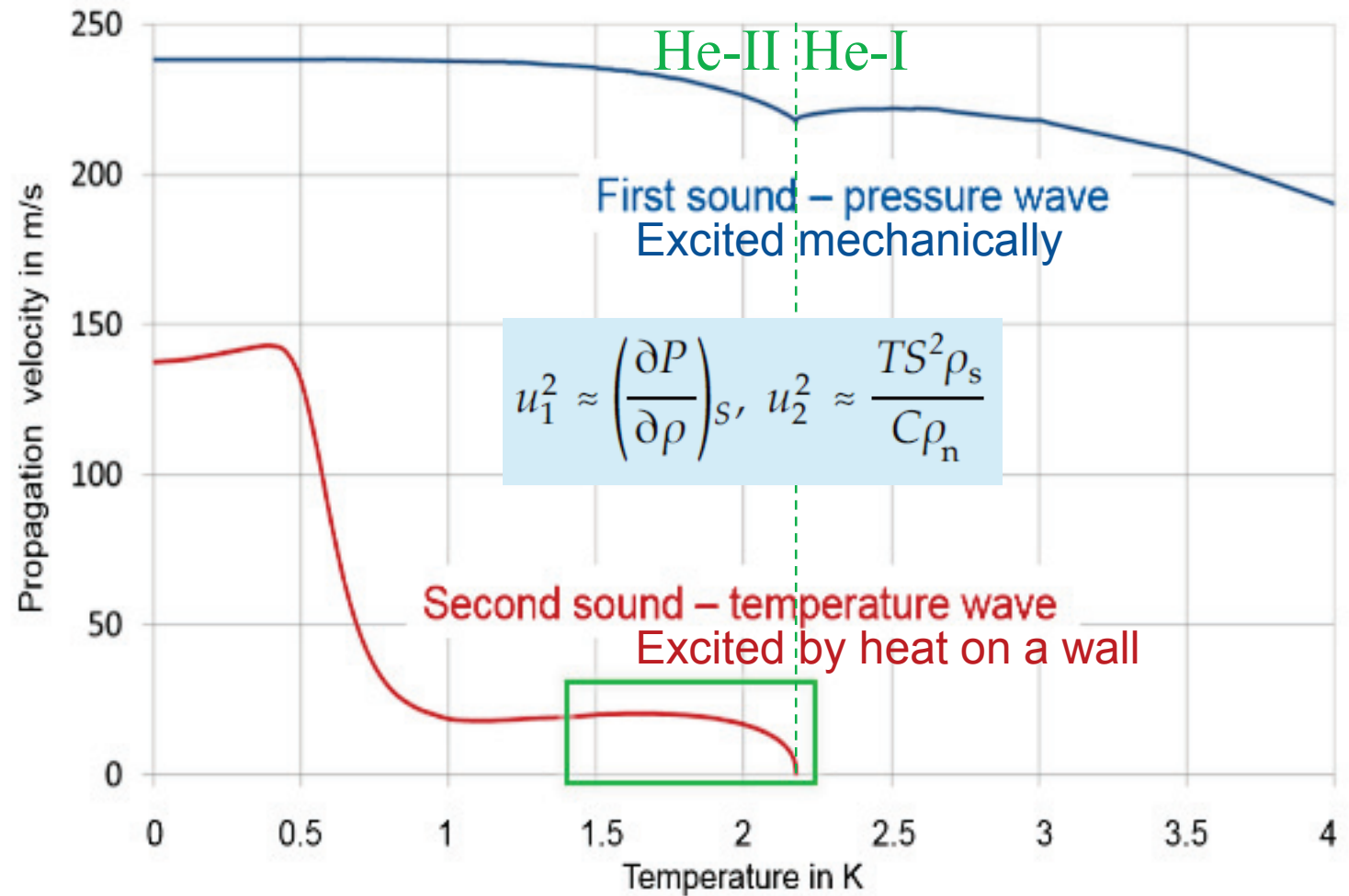
Second Sound in He-II and its detection

He-II and second sound physics



n: normal component particles

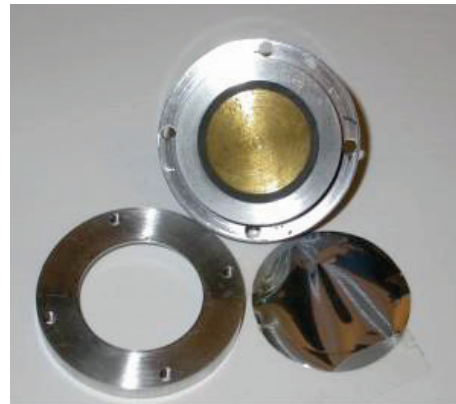
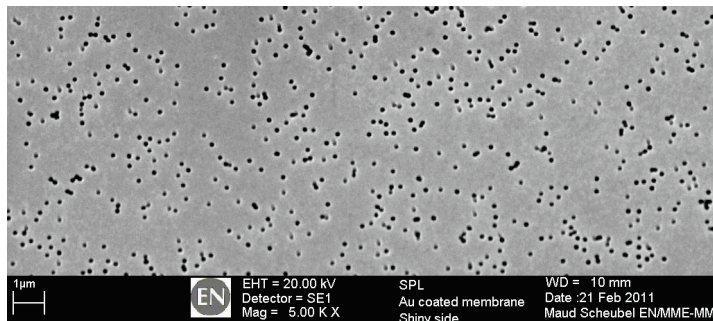
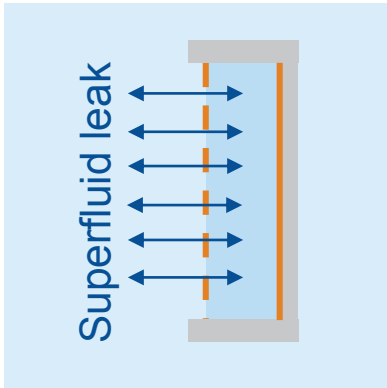
s: superfluid component particles



Second sound detection

Oscillating SuperLeak Transducers (OST)

- Sensing of the **relative movement of the two components**



Thermometry

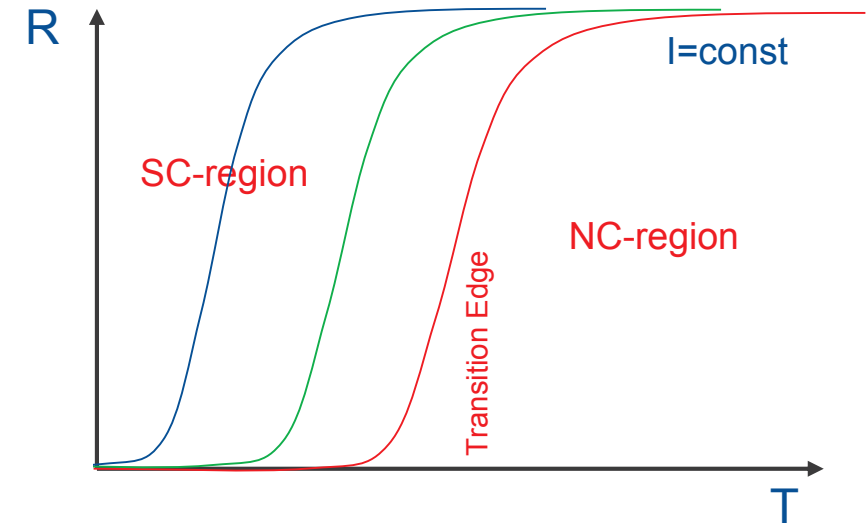
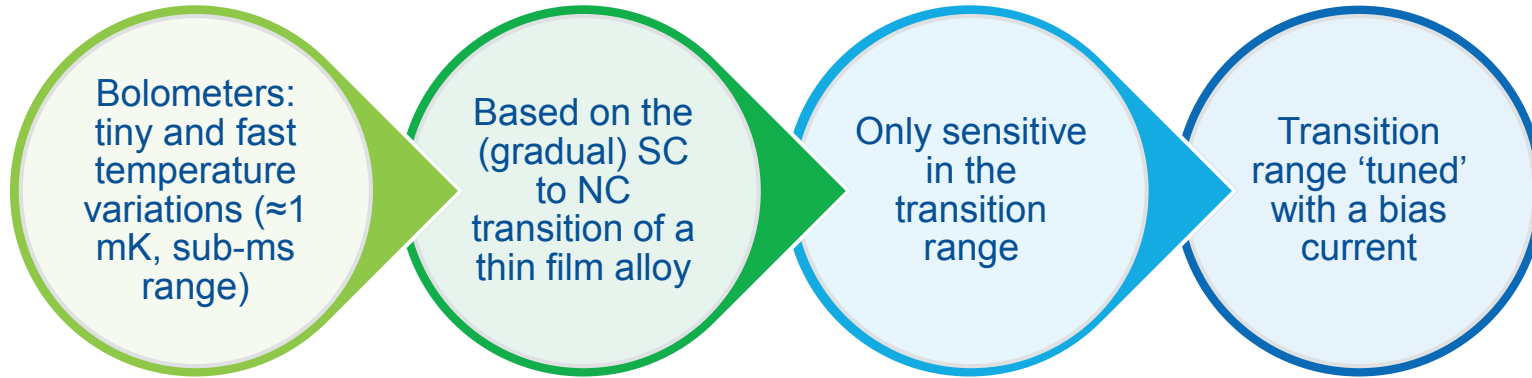
- Measurement of the **temperature** variation with fast response, highly sensitive thermometers
- **Commercial sensors** like Cernox bare chip sensors



Source:
Lakeshore website

- **Transition edge sensors**

Transition Edge Sensors



Transition Edge Sensors

Bolometers:
tiny and fast
temperature
variations (≈ 1
mK, sub-ms
range)

Based on the
(gradual) SC
to NC
transition of a
thin film alloy

Only sensitive
in the
transition
range

Transition
range 'tuned'
with a bias
current

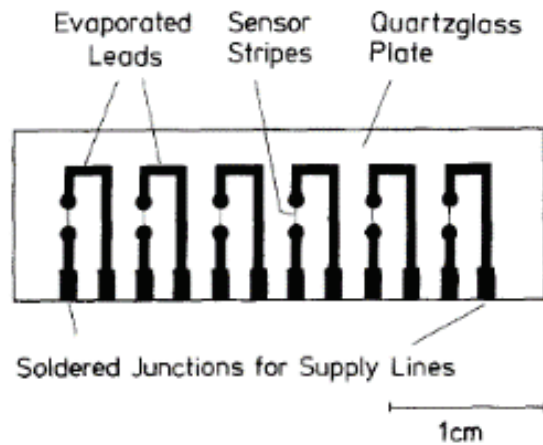
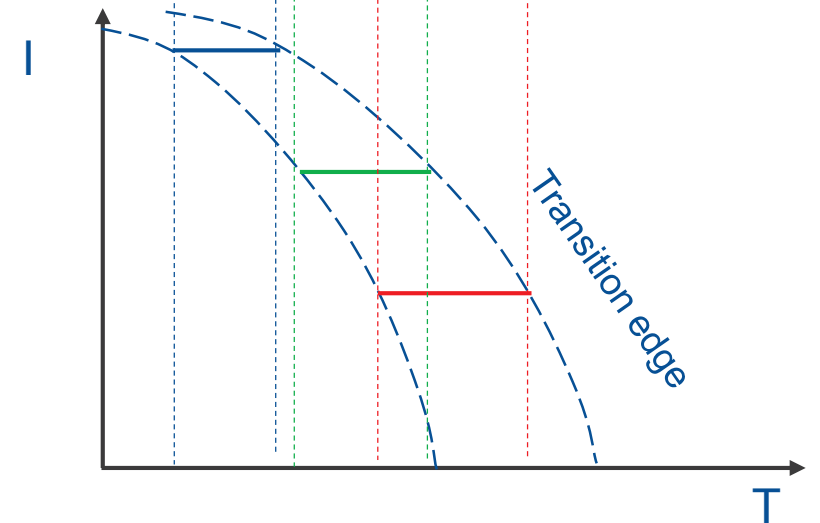
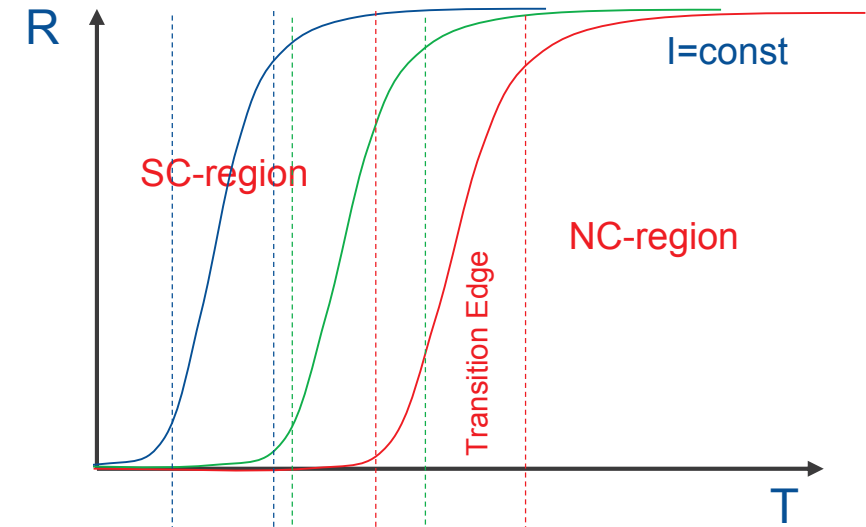
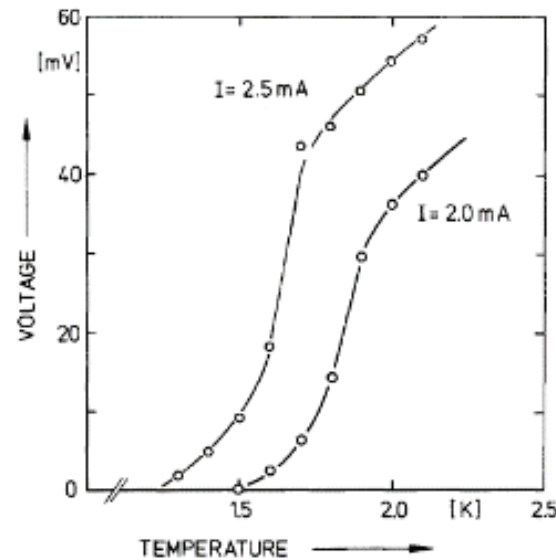


Fig. 1. Sixfold probe chip for second-sound measurement.



2nd sound detection, Au (20 nm) – Sn (100 nm)
thin film alloys are a proven material.

Source: H. Borner, Experimental Investigations on Fast Gold-Tin Metal Film Second-Sound Detectors and Their Application

Advantages of TES to OST

Electronics

- Simpler: 4-wire measurement is enough

Space resolution

- One can fabricate them practically as small as desired

Thermometry

- They could provide information on the quench heat flux

Signal

- Not polluted with the mechanical oscillations of the membrane

Reproducibility

- Can all the parameters involved in the fabrication process be controlled?

Project Objectives

Establish an in-house production method of TES at CERN → appropriation of the technology

Produce prototypes of TES

Cryogenic testing of TES at the Cryolab at CERN

- Characterisation of the SC transitions
- Second sound detection by TES

Deliver a TES sensing device

Design a large scale TES thermal mapping system

Validate TES quench localization on an SRF quenching system

Fabricating TES Prototypes in Au-Sn

Fabrication process

Not available commercially – In-house development

Need of an easy-going process to fabricate the TES

We used very up-to-date microfabrication clean room of **CMi/EPFL**



Drawing of the sensors

- On any CAD program
- Sensor array on standard wafer (10 cm diameter)

Process flow

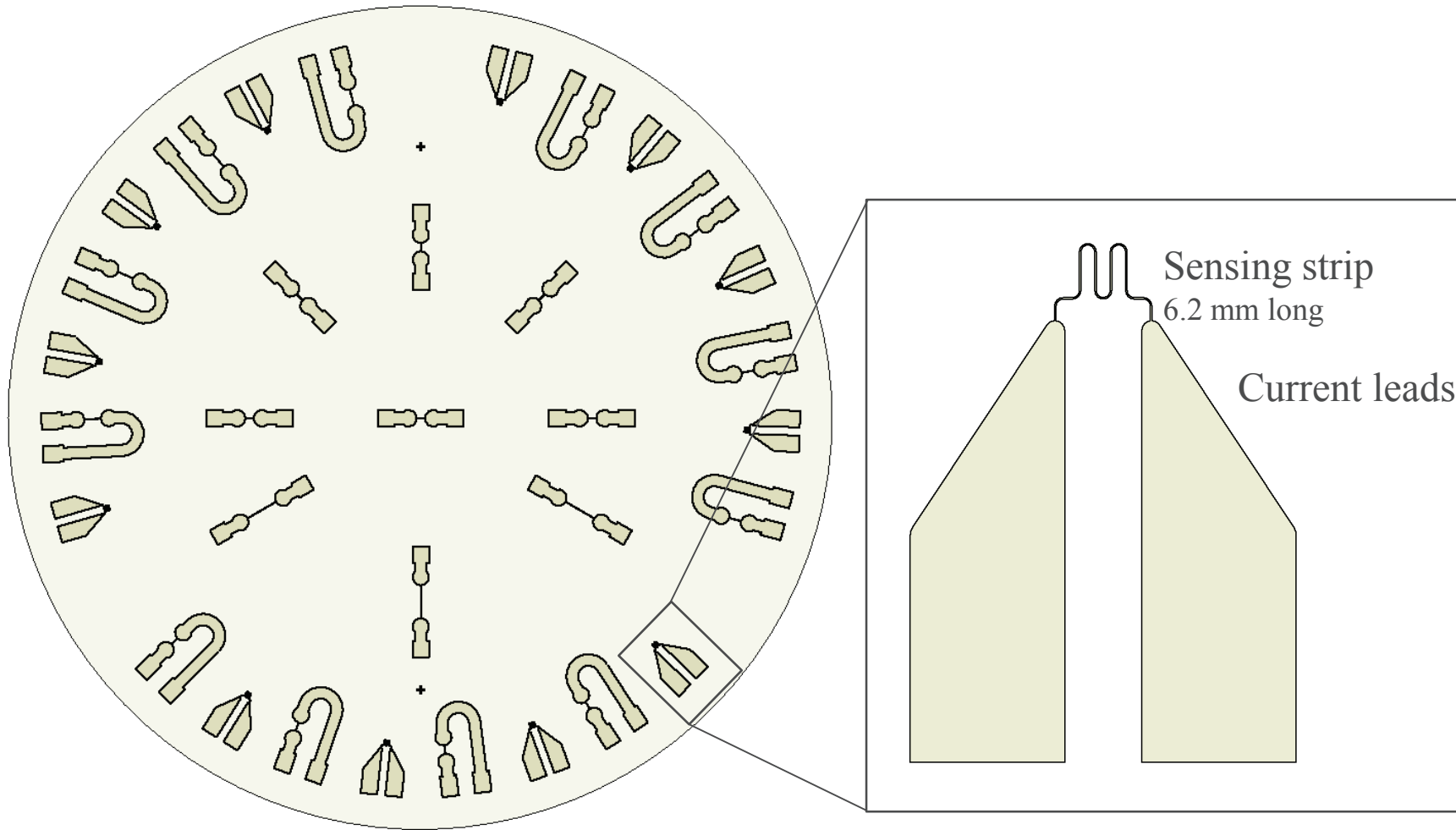
- Automatized photolithography
- Leads and strips of the same material

Cabling

- Soldering with Indium
- Twisted 4-wires, by hand and without heat

Process description	Cross-section after process
Substrate: <i>Borofloat 33</i> <i>Coating – positive resist</i> Machine: <i>ACS 200</i>	
<i>LASER Writing</i> Machine: <i>VPG 200</i>	
<i>Developing</i> Machine: <i>ACS 200</i>	
<i>Metal Evaporation</i> Metals: <i>Au-Sn</i>	
<i>Lift-off</i>	

Prototype wafer design



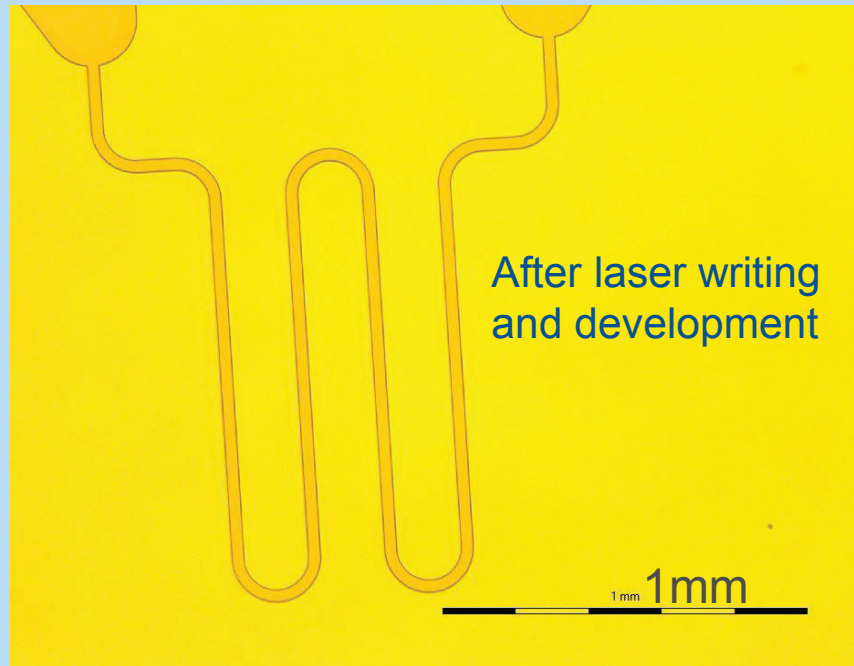
Strips

- 30 μm wide
- Variable length (1 to 7 mm)
- Meandering design
- Sensing area $\approx 1 \text{ mm}^2$

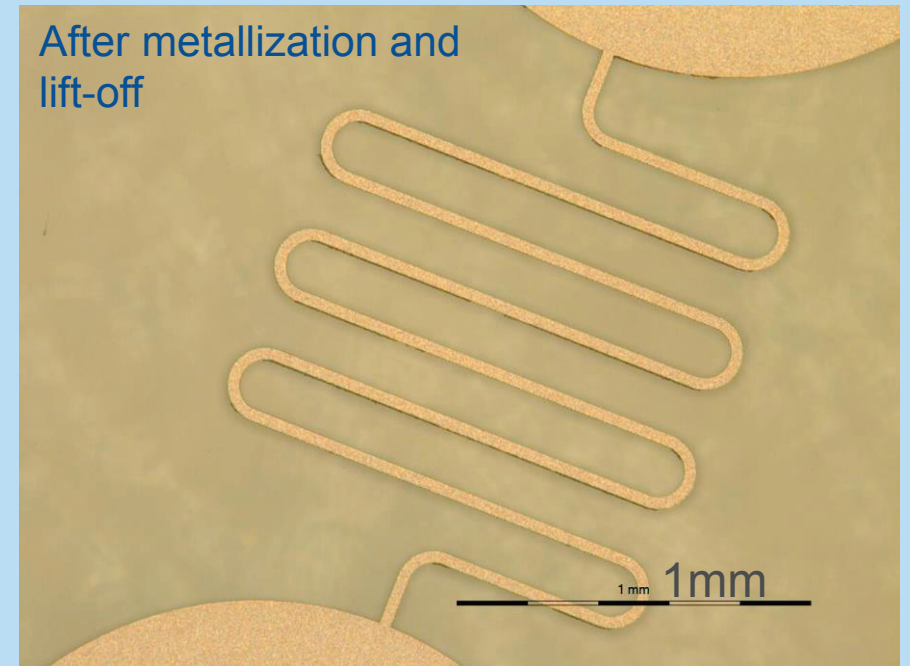
Leads

- Oriented for cabling
- Big enough for cabling
- Same material as sensor (low $J \rightarrow$ SC always)
- Pads for Indium cold weld or pressed contact

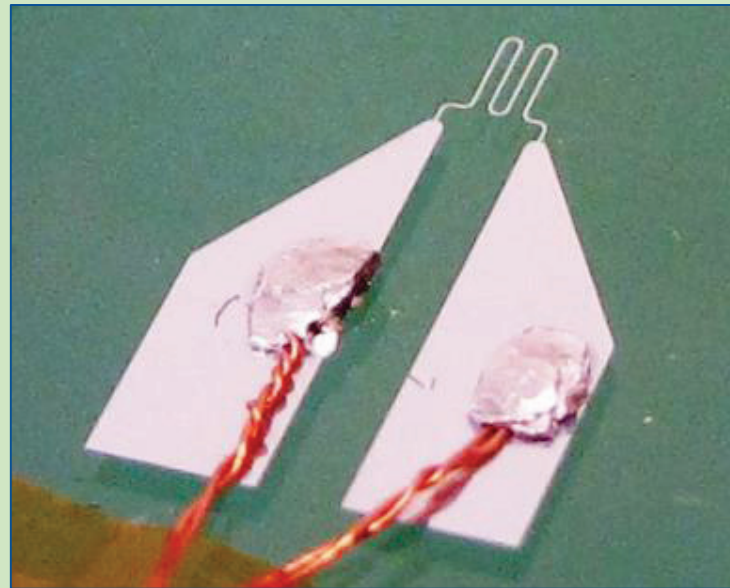
Fabrication results



After metallization and lift-off



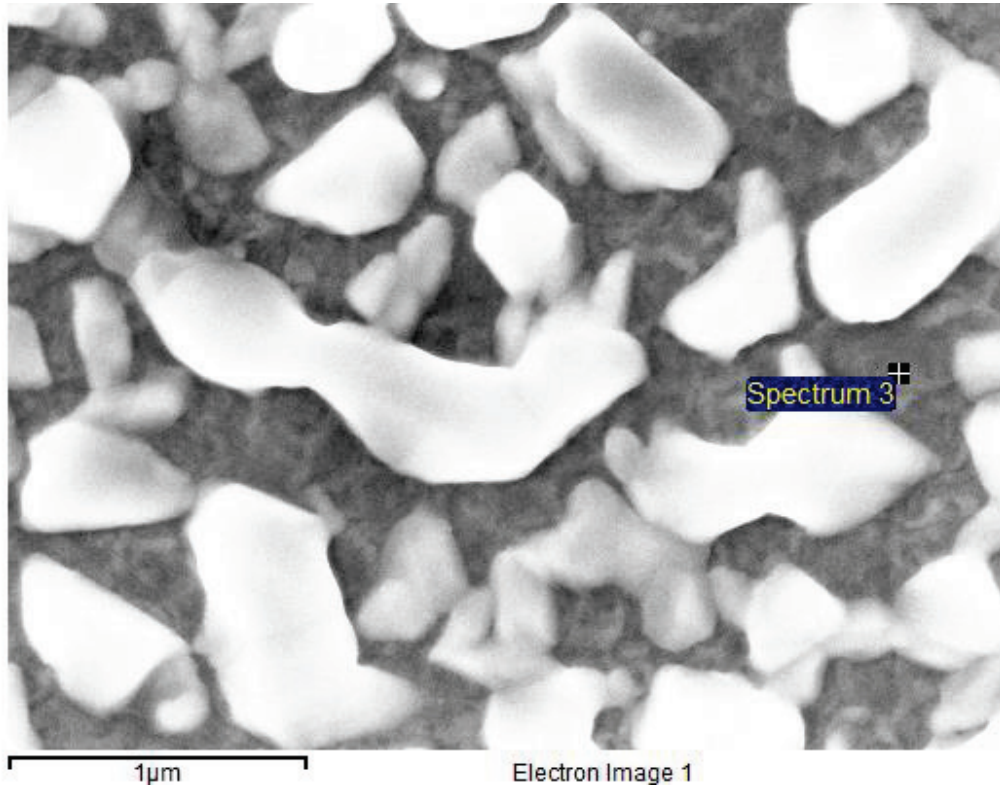
Sensor cabling



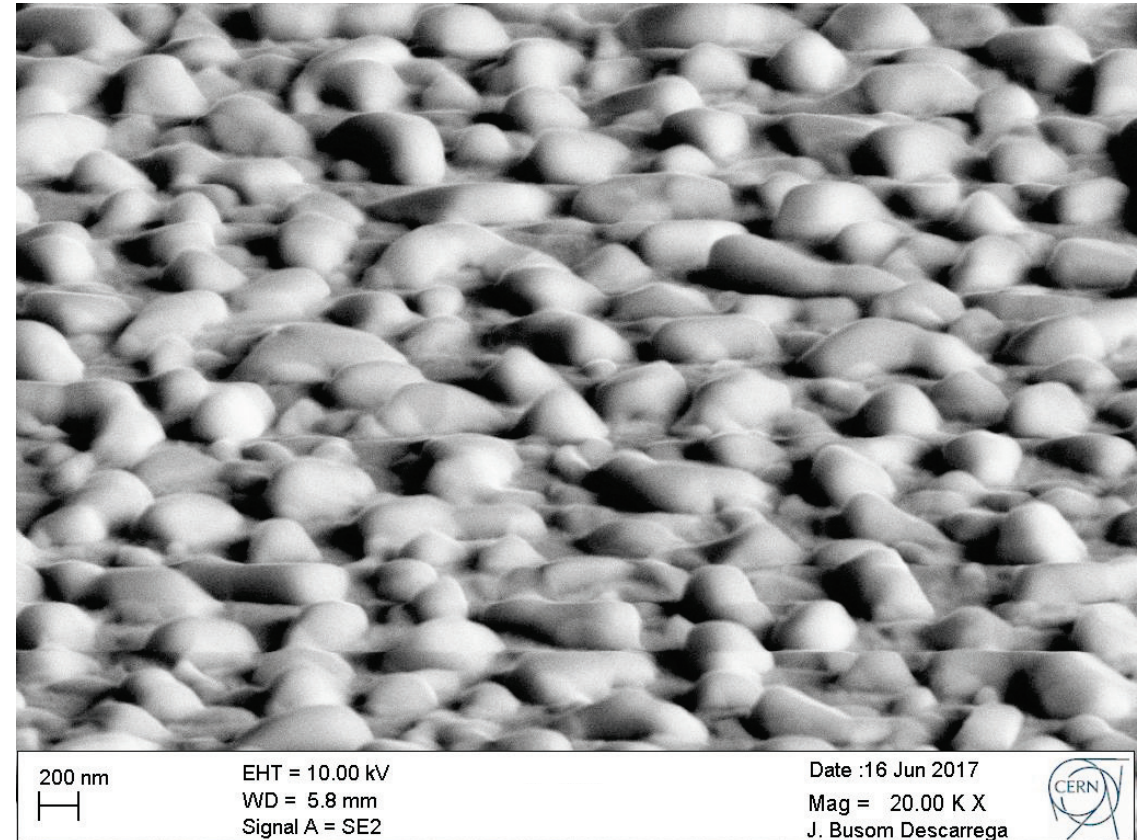
Instrumented wafer
4 wire measurement
configuration

Indium soldering

Thin film microstructure

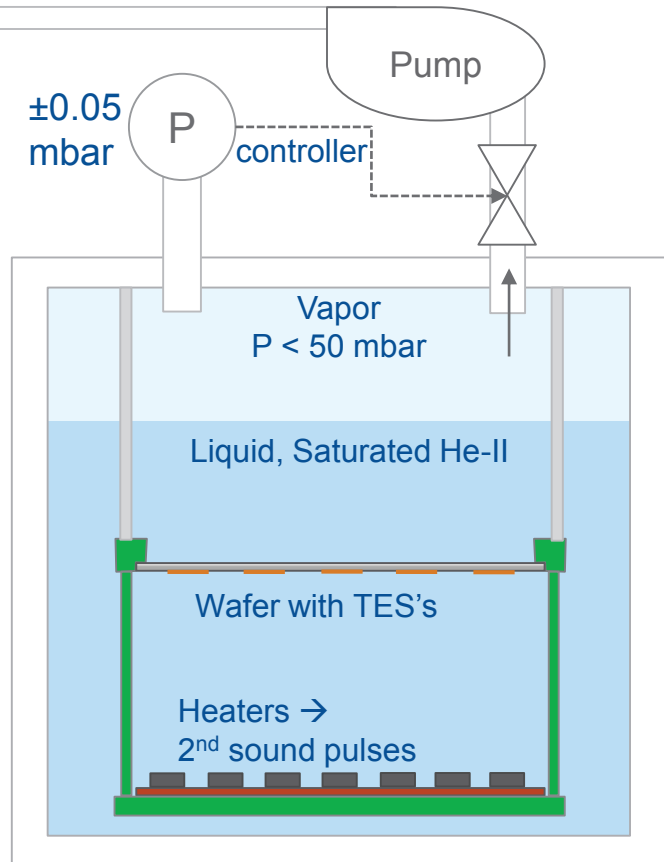


The bright structures have a much higher content of Sn (AuSn_4 or Sn) than the dark background (AuSn_2)

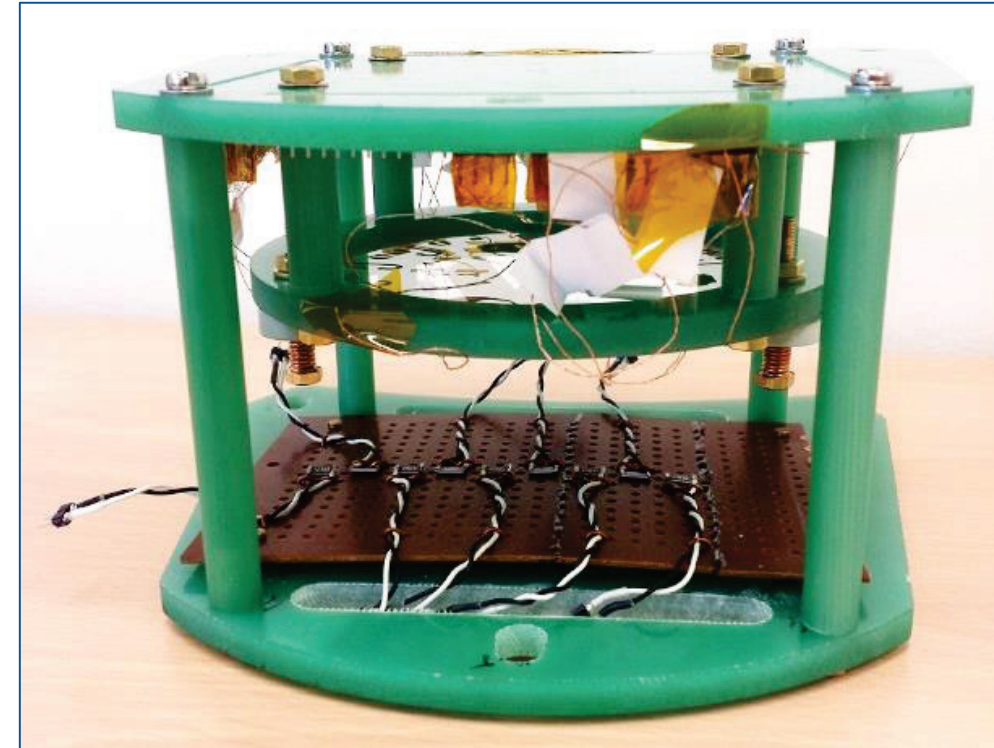
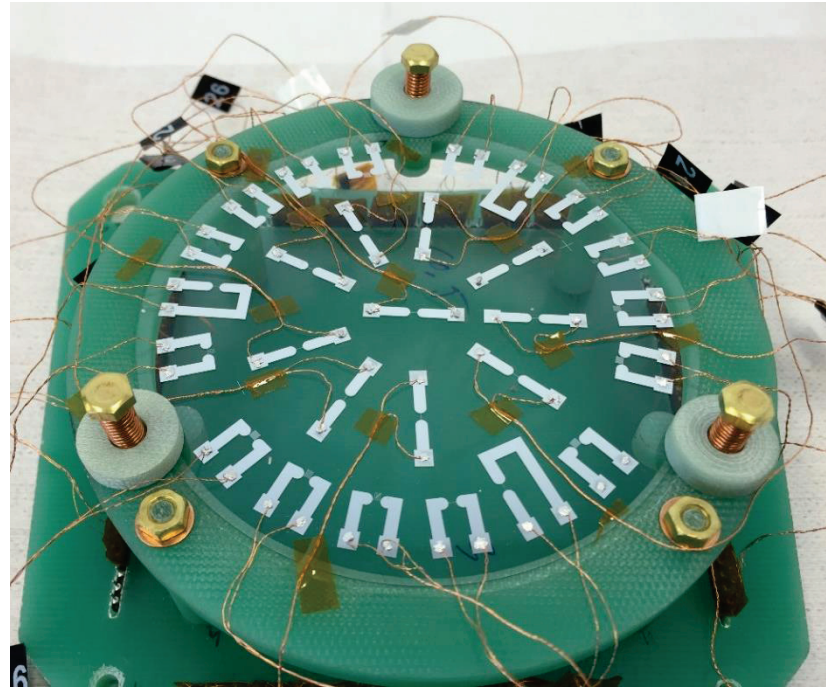


Cryogenic testing

Testing of TES at the Cryolab



Helium p-T curve is the T standard (IST90) in the LHe range



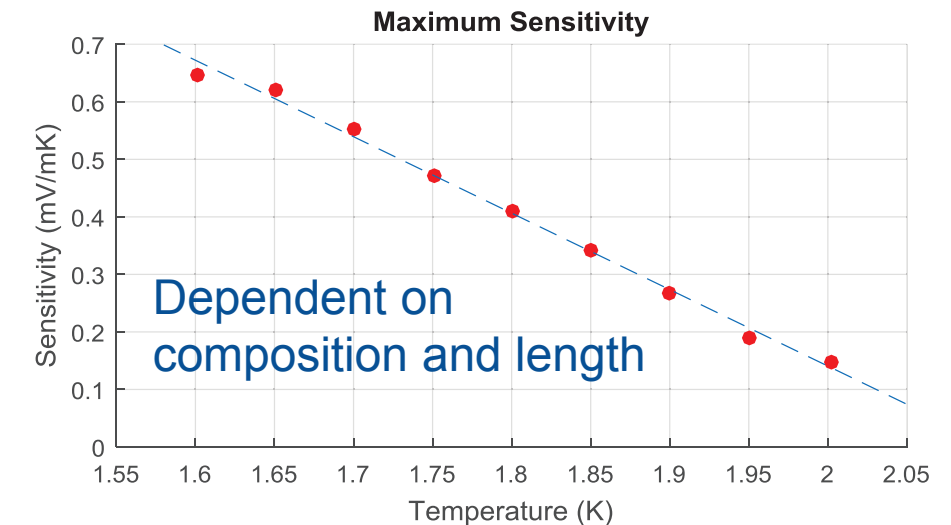
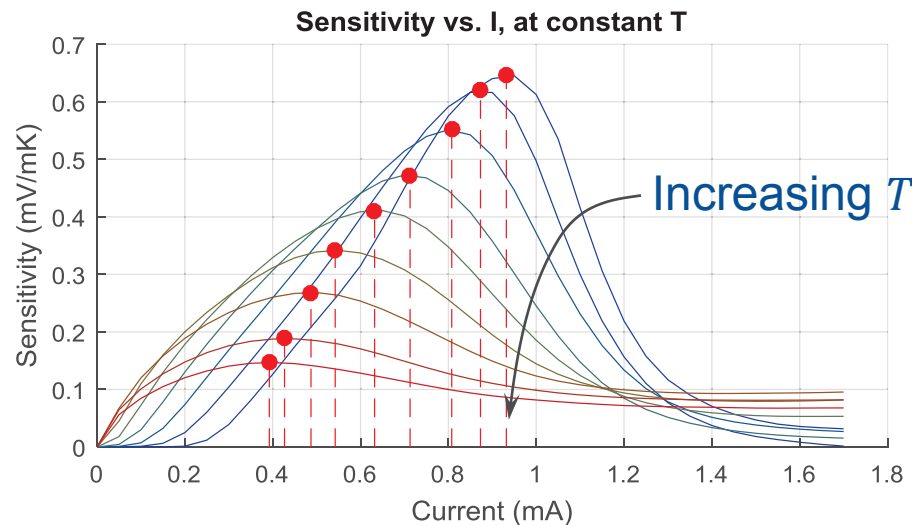
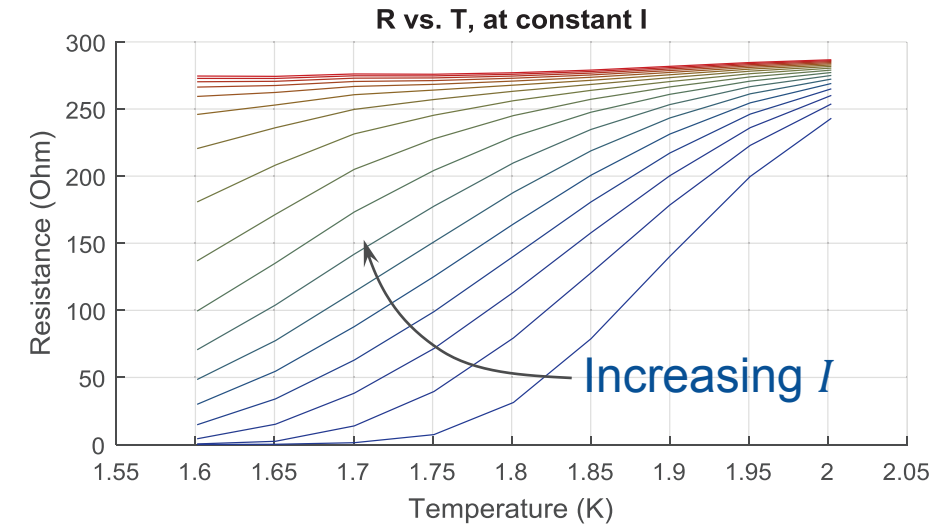
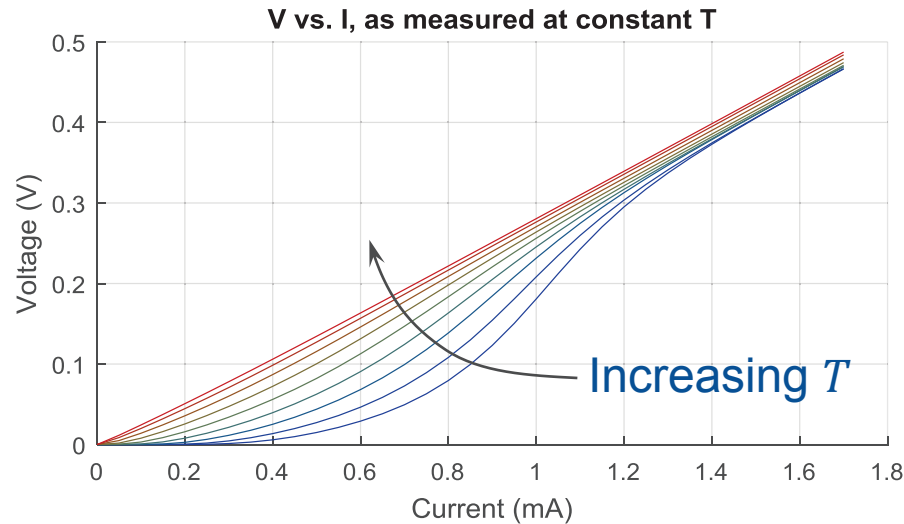
TES Characterization

Pressure steps:
750 to 3150 Pa
(1.6 to 2.0 K)

Current sweeps:
0 to 1.7 mA

Voltage recording =>
Resistance

Sensor strip
20 nm Au –
100 nm Sn

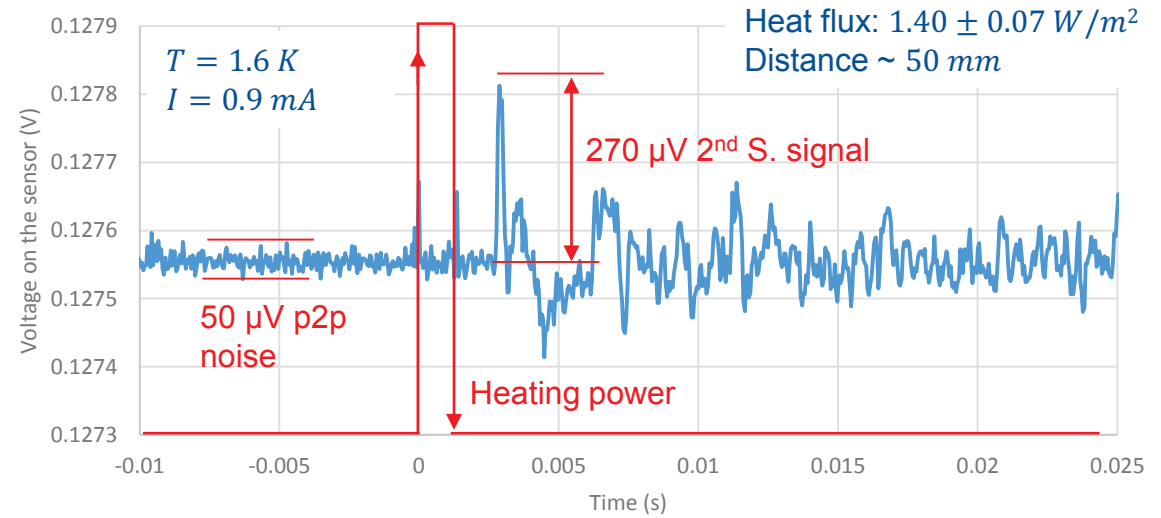
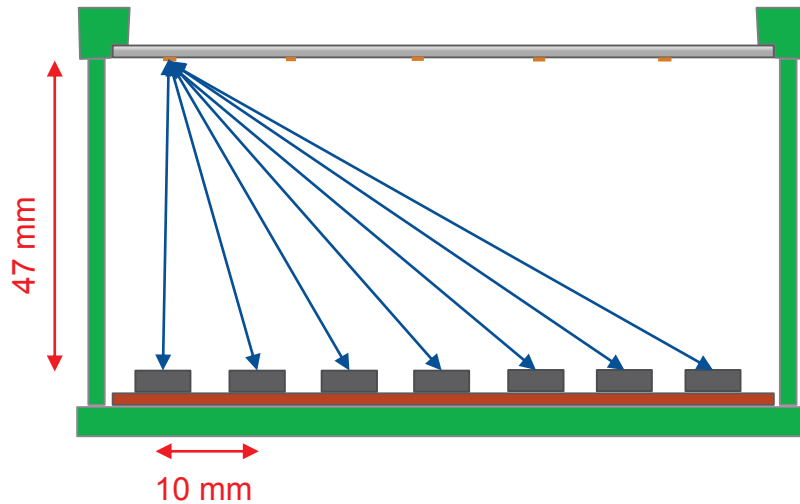


Second sound measurements with TES

Pulses by resistive heaters

Different distances

Sensors biased at constant current



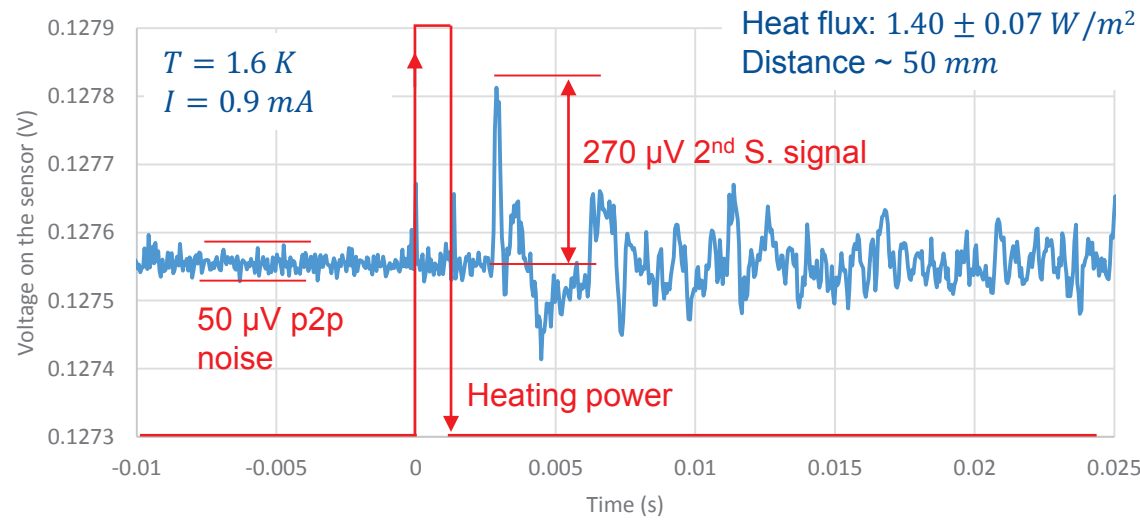
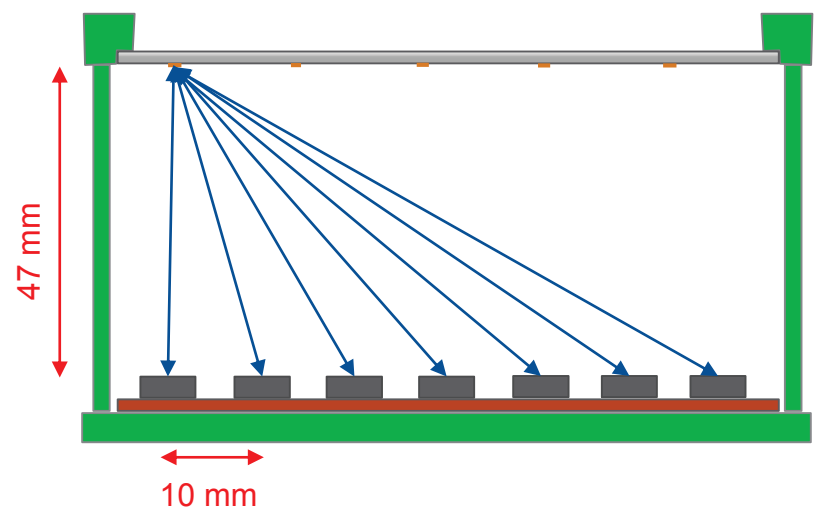
The signal was measured WITHOUT any electronic treatment (20 kHz sampling rate on NI compact DAQ)

Second sound measurements with TES

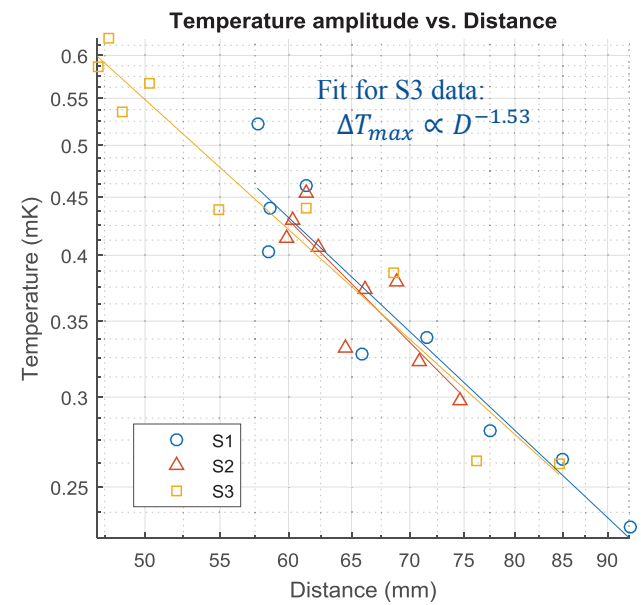
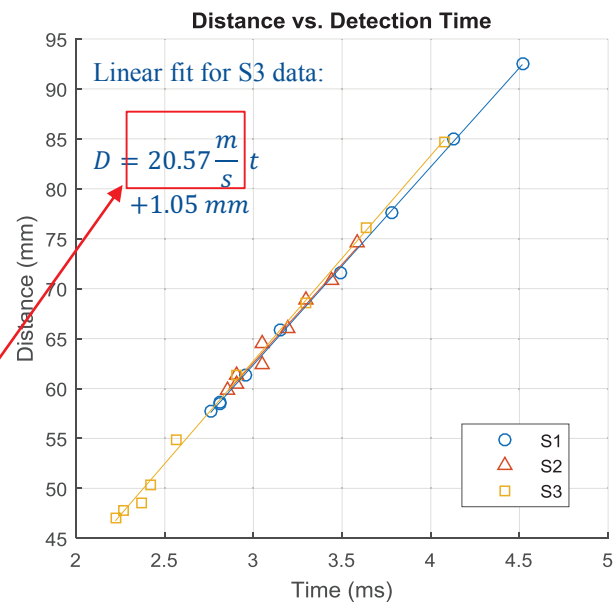
Pulses by resistive heaters

Different distances

Sensors biased at constant current



The second sound signal is clearly identified and the velocity value corresponds to literature.



Further studies on TES thin film

Variation of composition and its impact of TES quality

Other material combinations

Reproducibility

Effect of adhesion-improving pre-layer on the TES performance

Next steps in R&D

Comparative study TES-OST

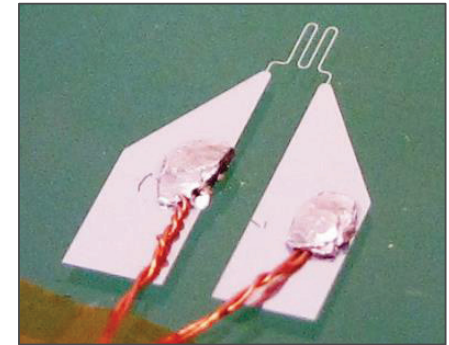
Fully characterise the two types of sensors

- in a common set-up
- in the same conditions

Appreciate differences in...

- Angular response
- Effect of distance from the source
- Response to source intensity
- Time response features

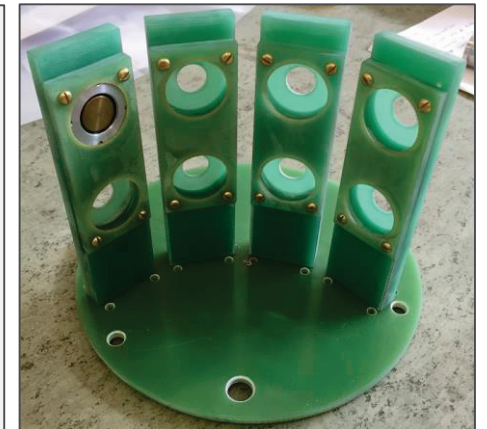
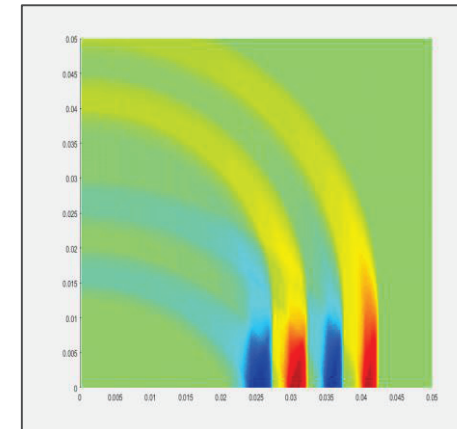
Assess the advantages and drawbacks of each of them



Second sound 3D propagation study

Spatial structure of a second sound wave from planar heater

- Modelling
- Experimentally



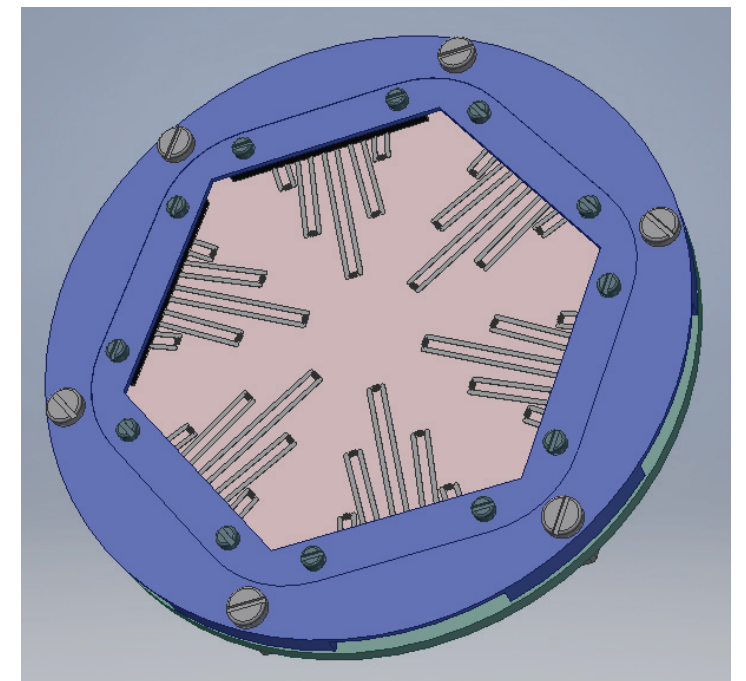
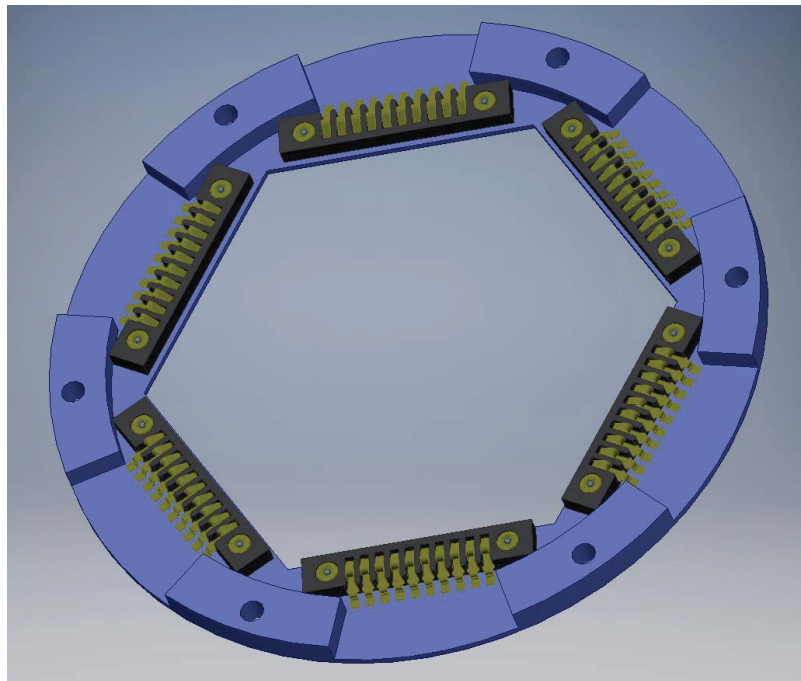
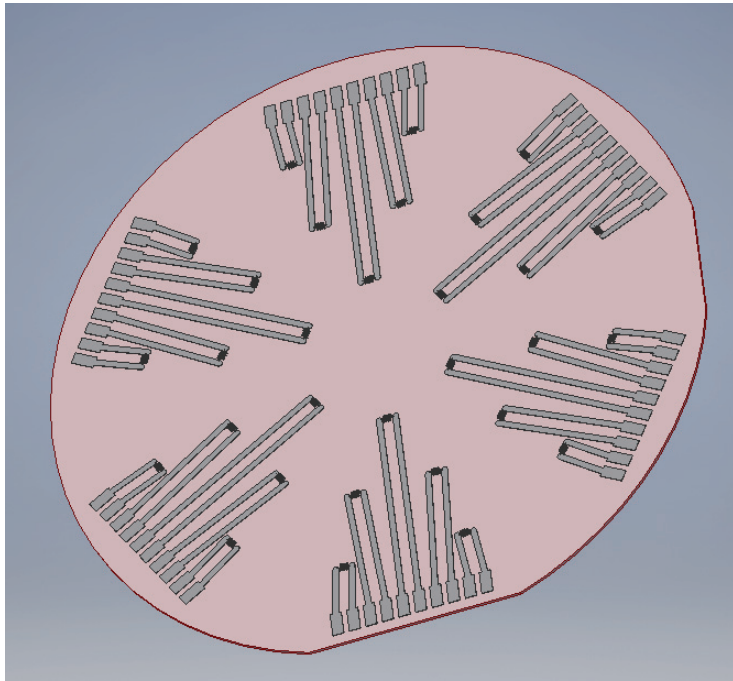
Towards Thermal Mapping Instruments

TES camera array

A **compact** multi-sensor device of sufficient size to do thermal mapping with.

A network of **independent sensors** is proposed.

The **robustness** is provided by a GFE frame. The **connection is simplified** with spring connectors. The fragility of the film needs to be dealt with, specially at **electrodes**.

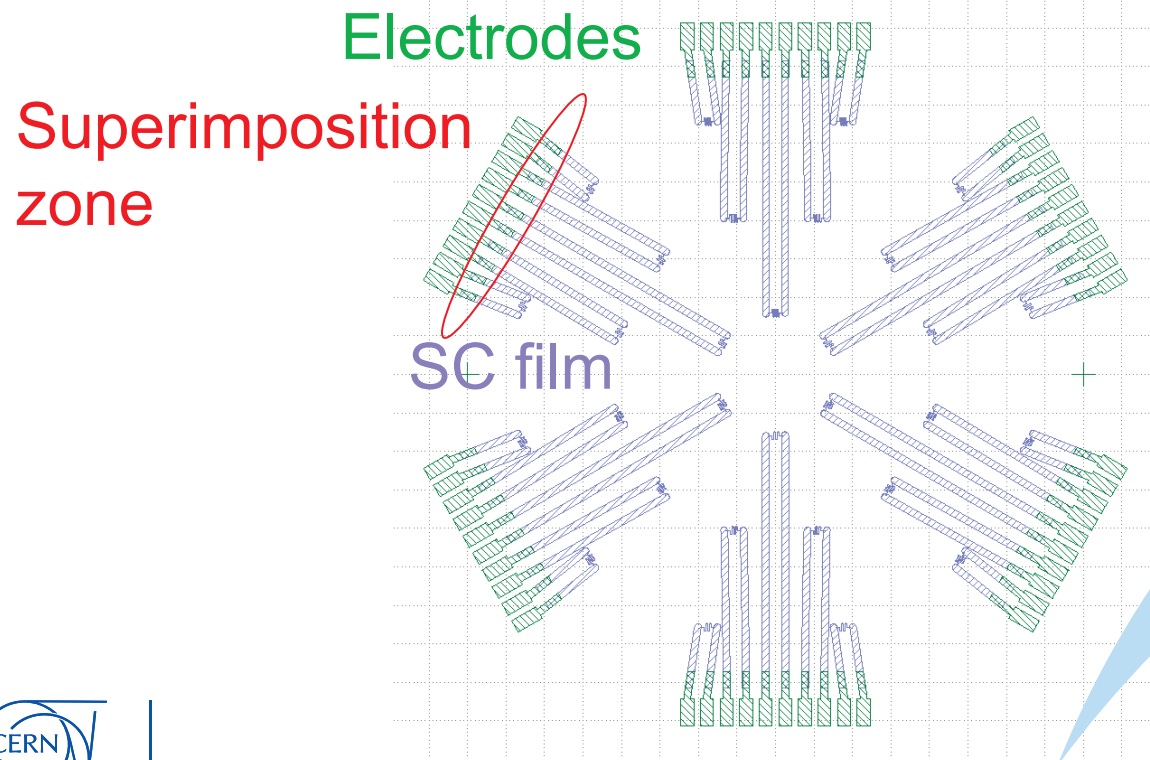


TES camera array: electrodes

More resistant electrodes can be obtained with a thin film of Ti and Au: we tested 20 nm – 80 nm thickness. The adhesion is sufficient.

Two photolithography processes: one for electrodes; one for sensors.

Micrometric alignment performed for the second laser writing process.



- Photolithography Electrodes
 - PR Coating
 - Writing
 - Developing
 - Thin Film (Ti-Au)
 - Lift-off

- Oxygen plasma cleaning
 - To eliminate eventual remaining solvent and PR impurities
 - Low intensity, not to damage the thin film

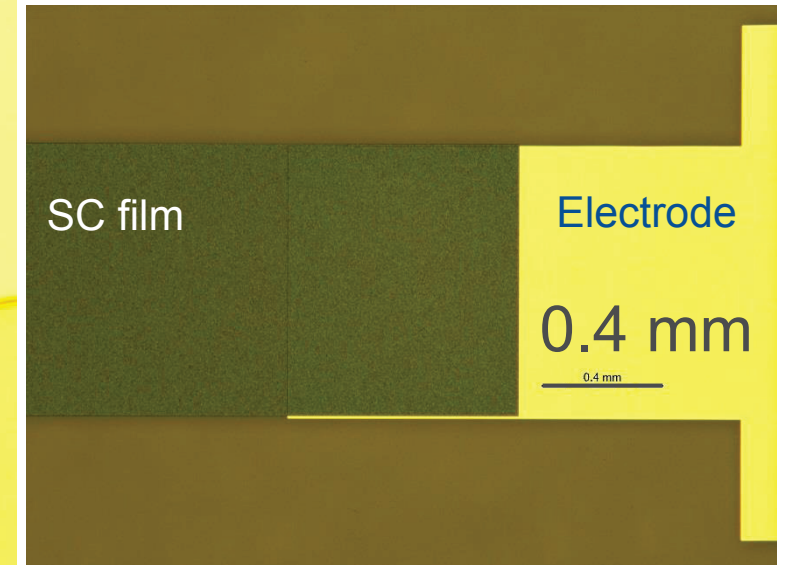
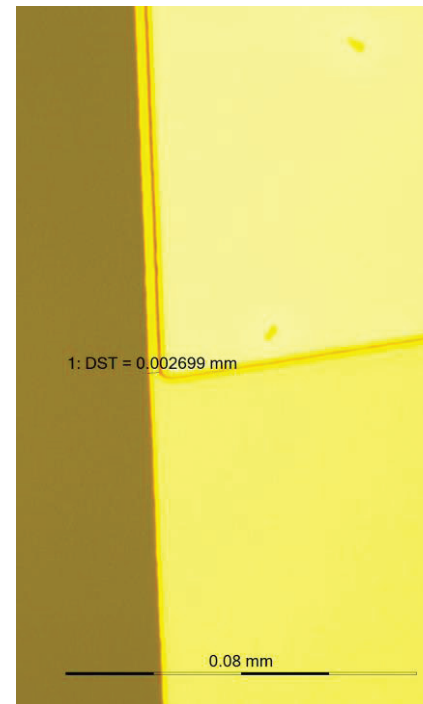
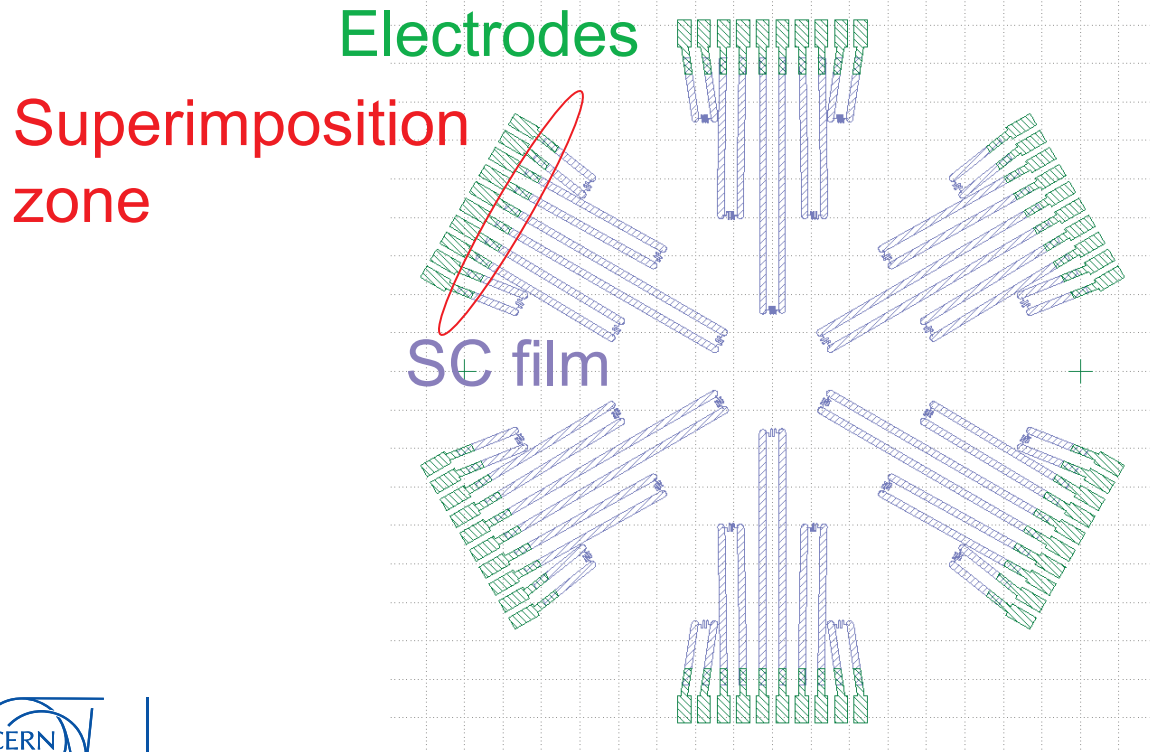
- Photolithography Sensors
 - PR Coating
 - Writing (with micrometric alignment)
 - Developing
 - Thin Film (Au-Sn or Cu-Sn)
 - Lift-off

TES camera array: electrodes

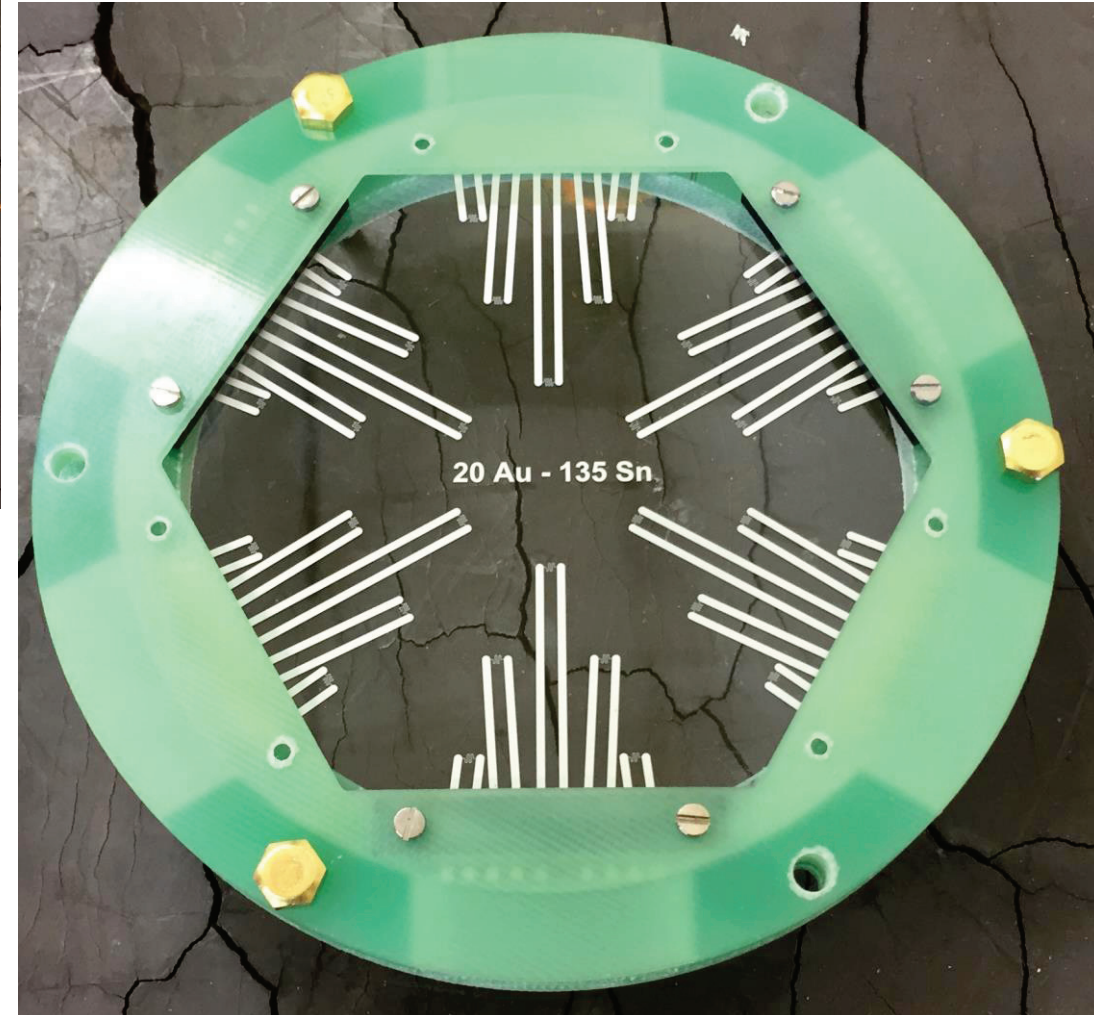
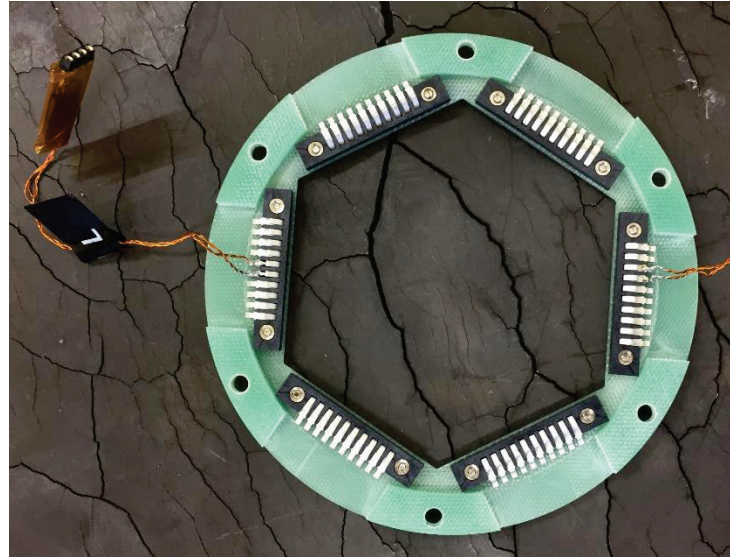
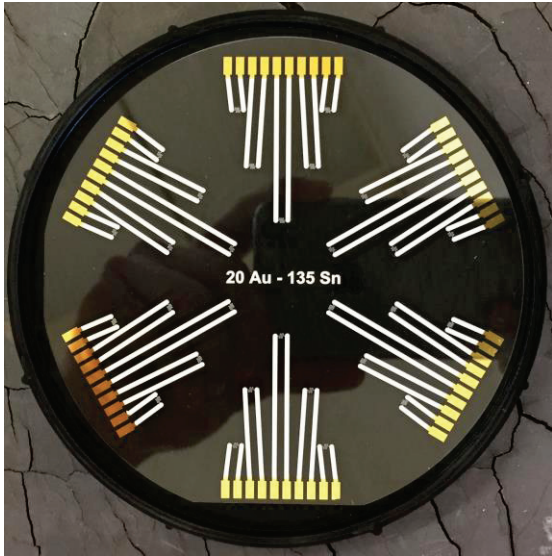
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TES camera array: prototype



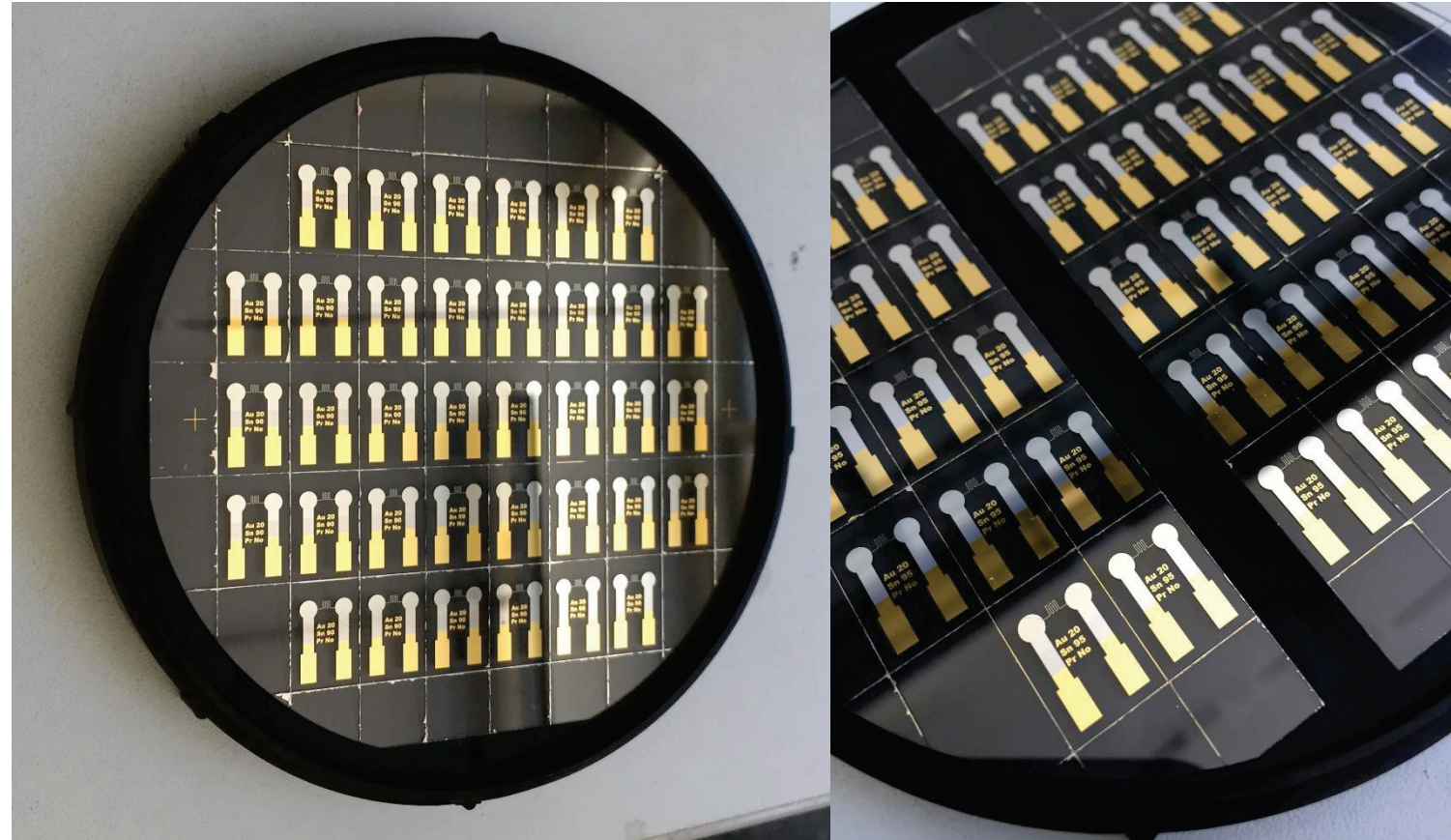
Stand-alone TES chips

Wafers have already been produced to test the method

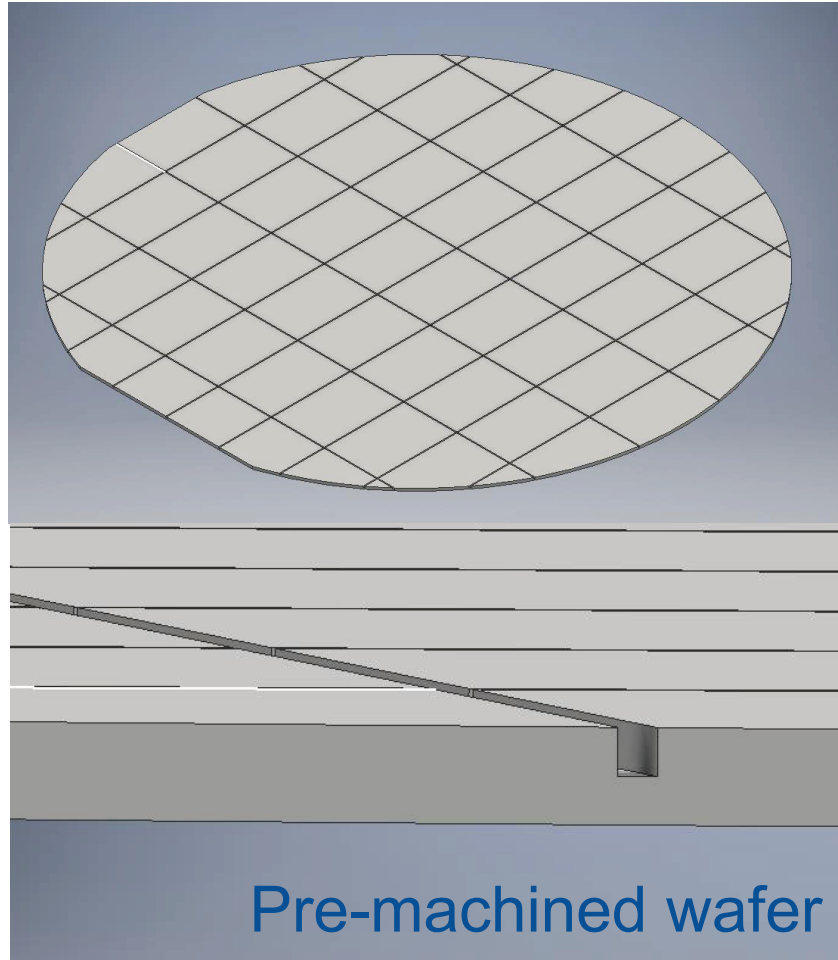
- Pre-diced cutting lines
- Thicker coating
- Laser more intense
- Careful manipulation

The results is satisfying

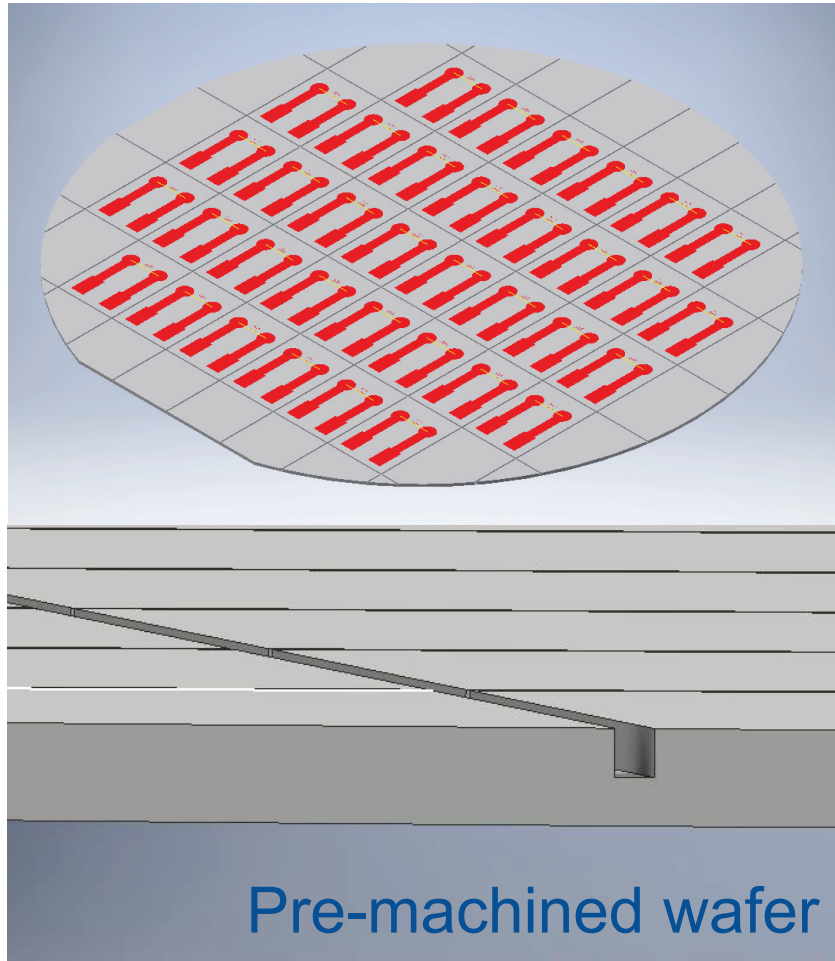
- Good geometrical quality
- Easy to separate



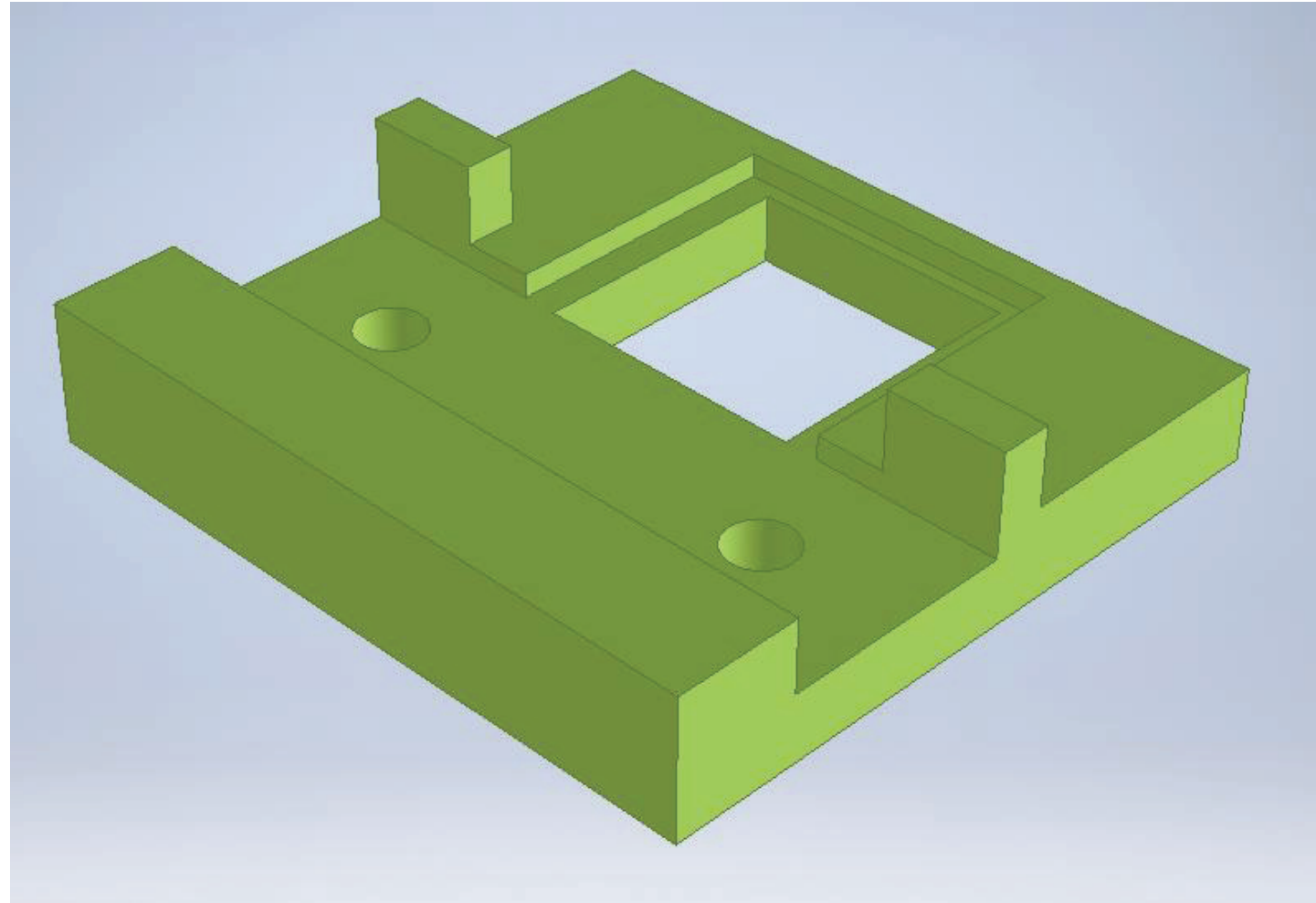
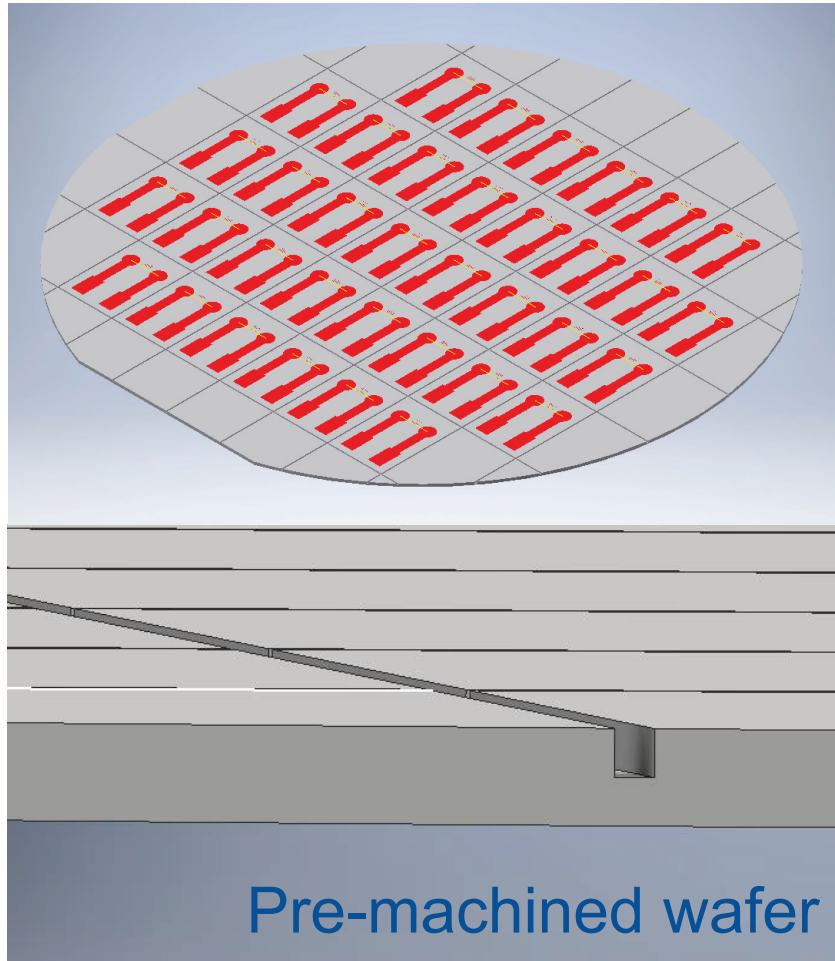
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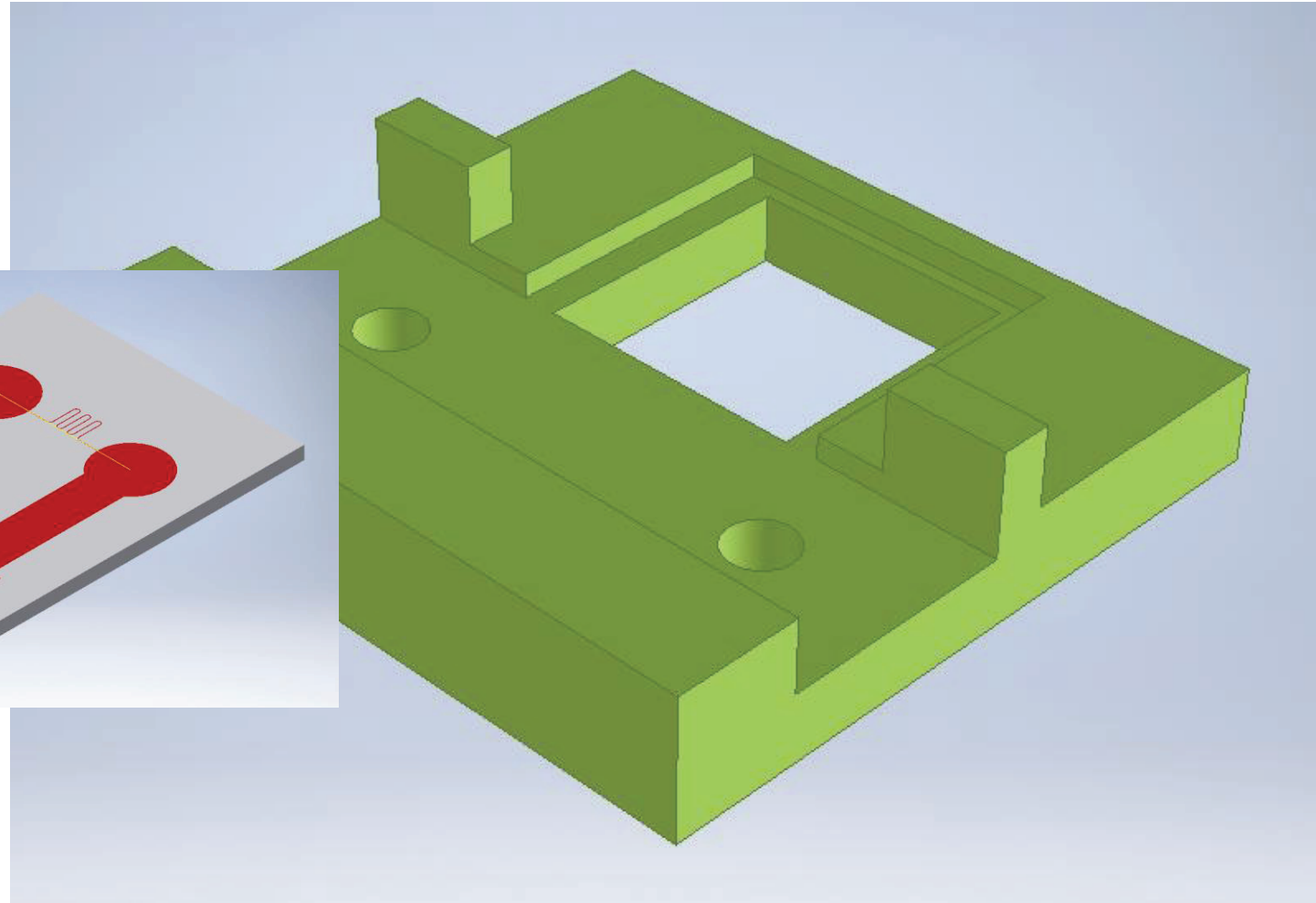
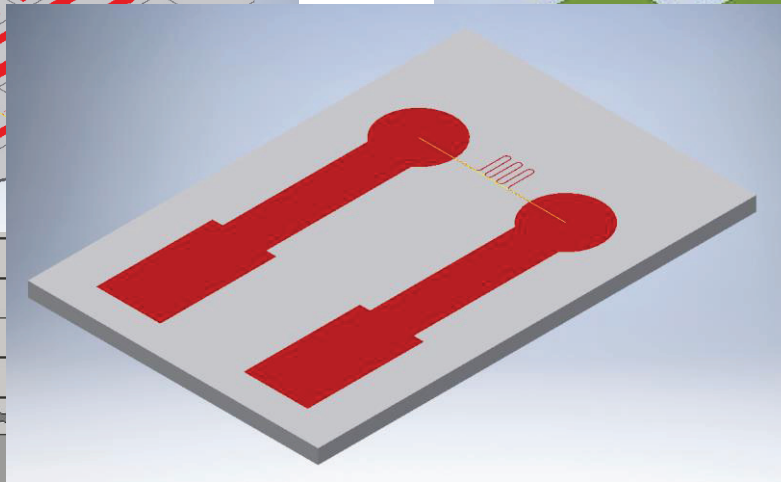
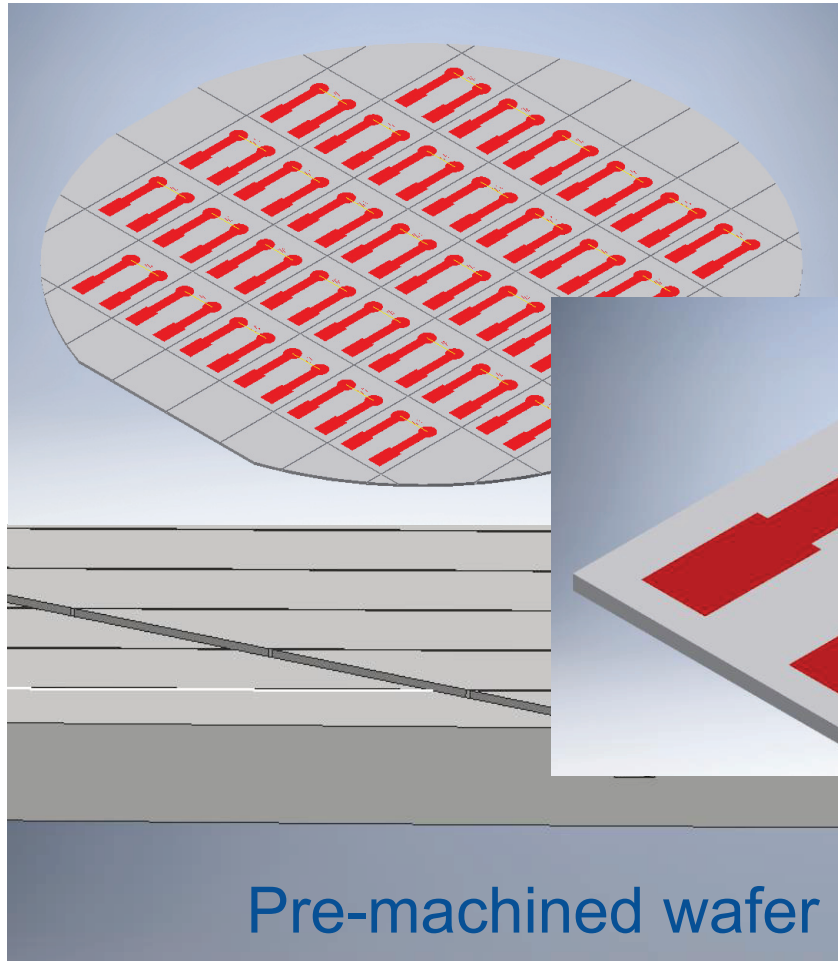
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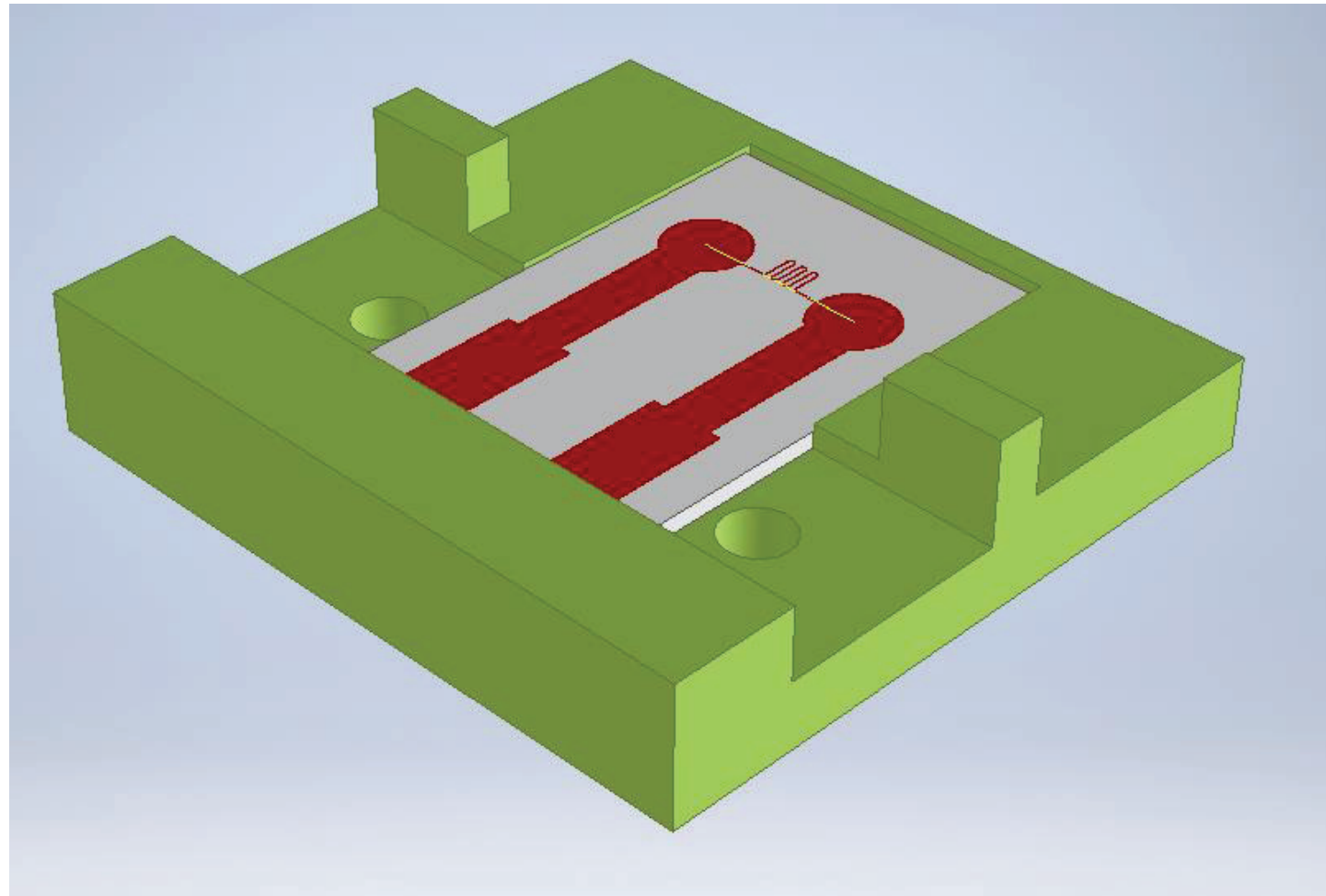
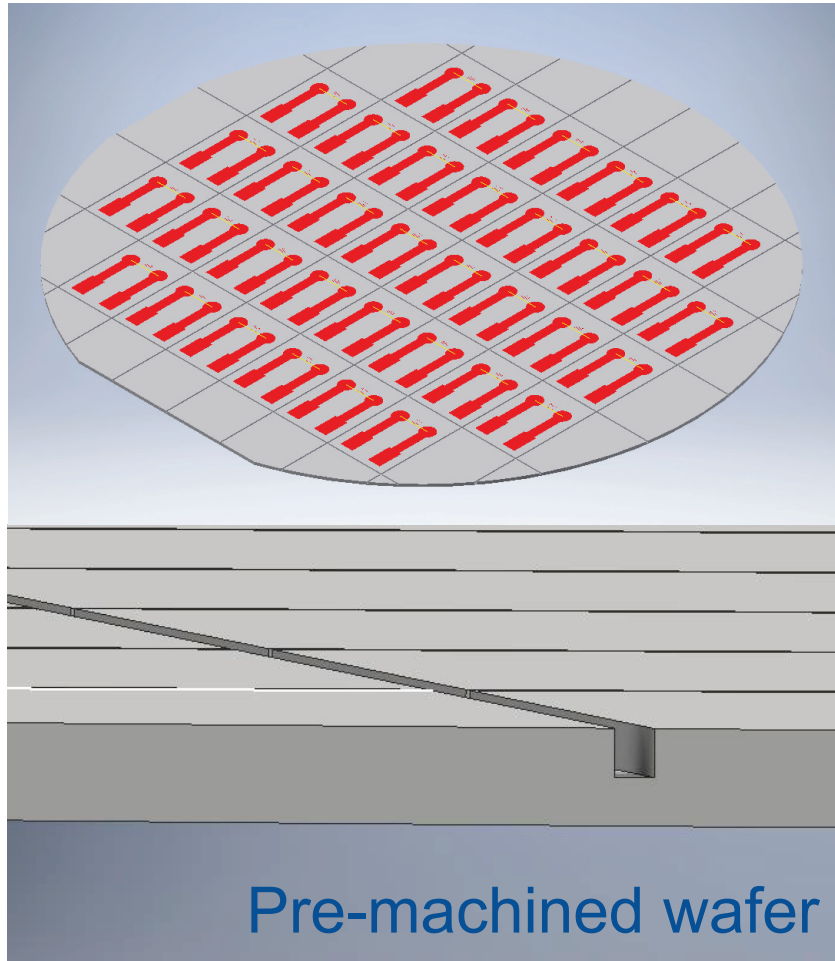
Stand-alone TES chips



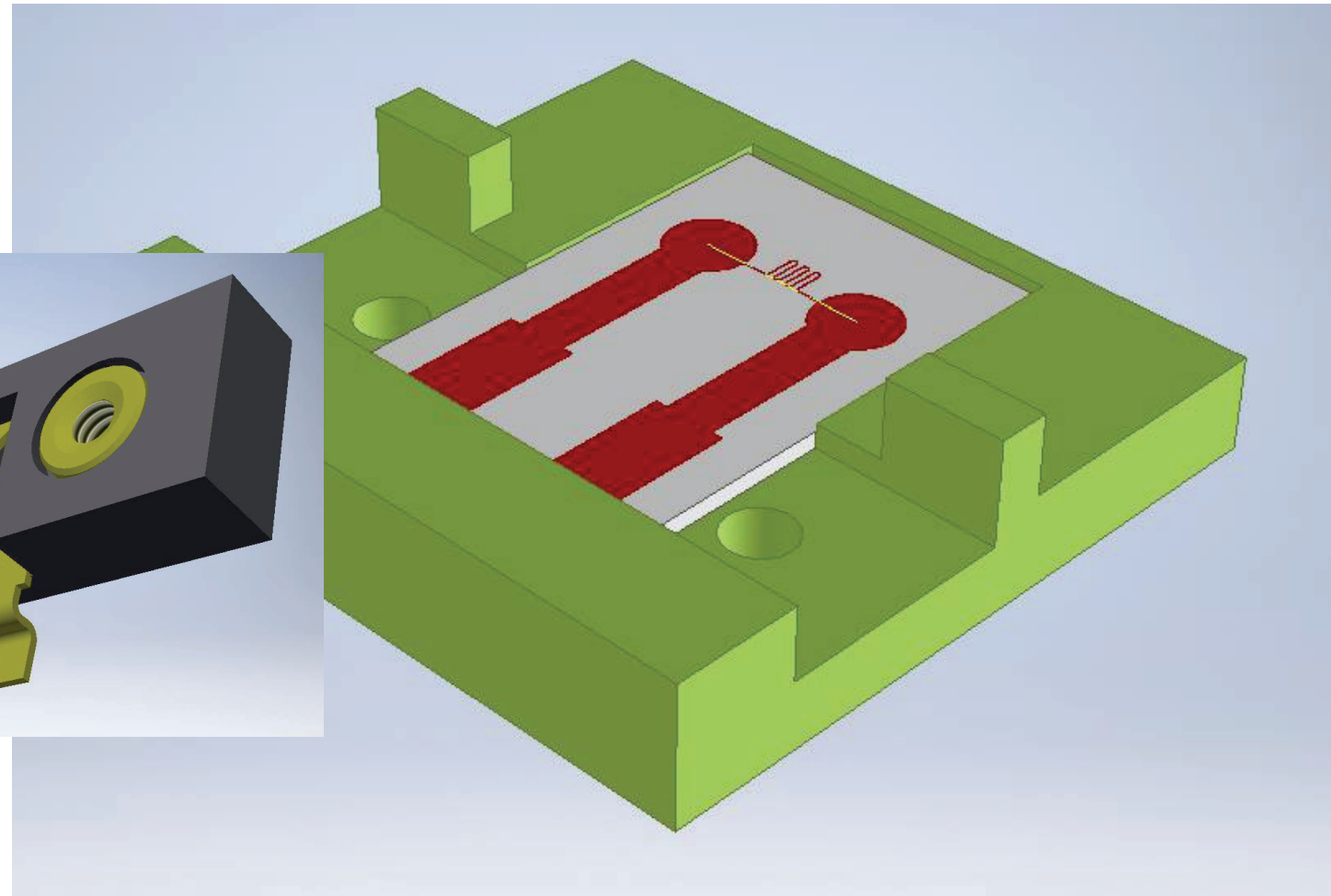
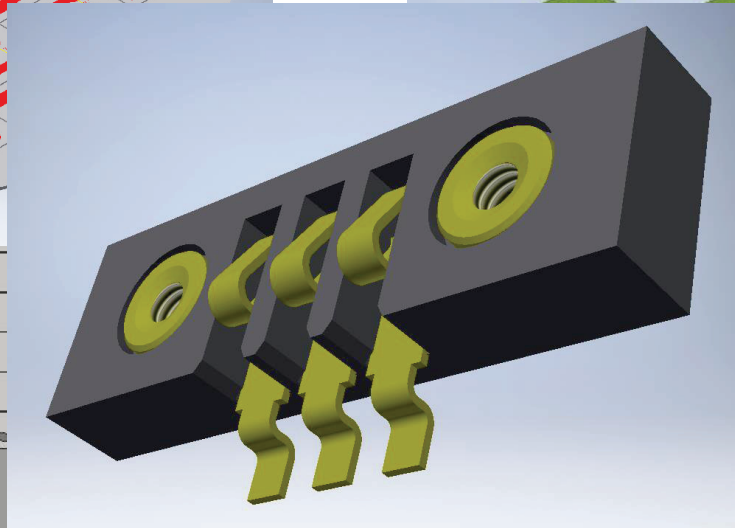
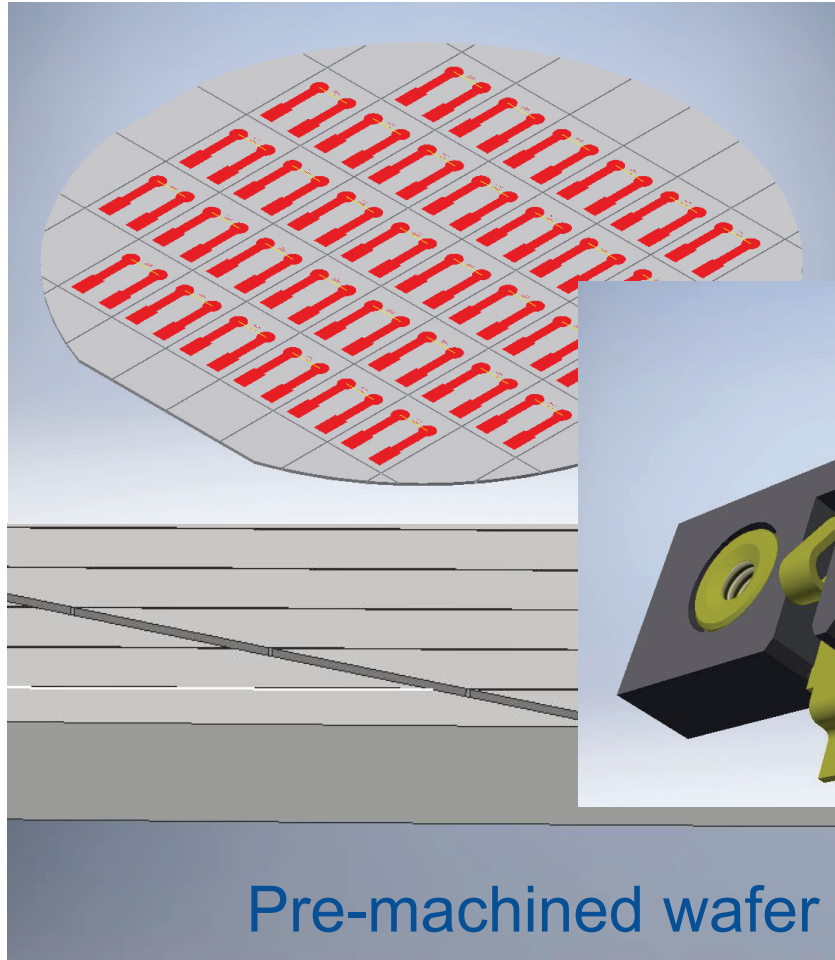
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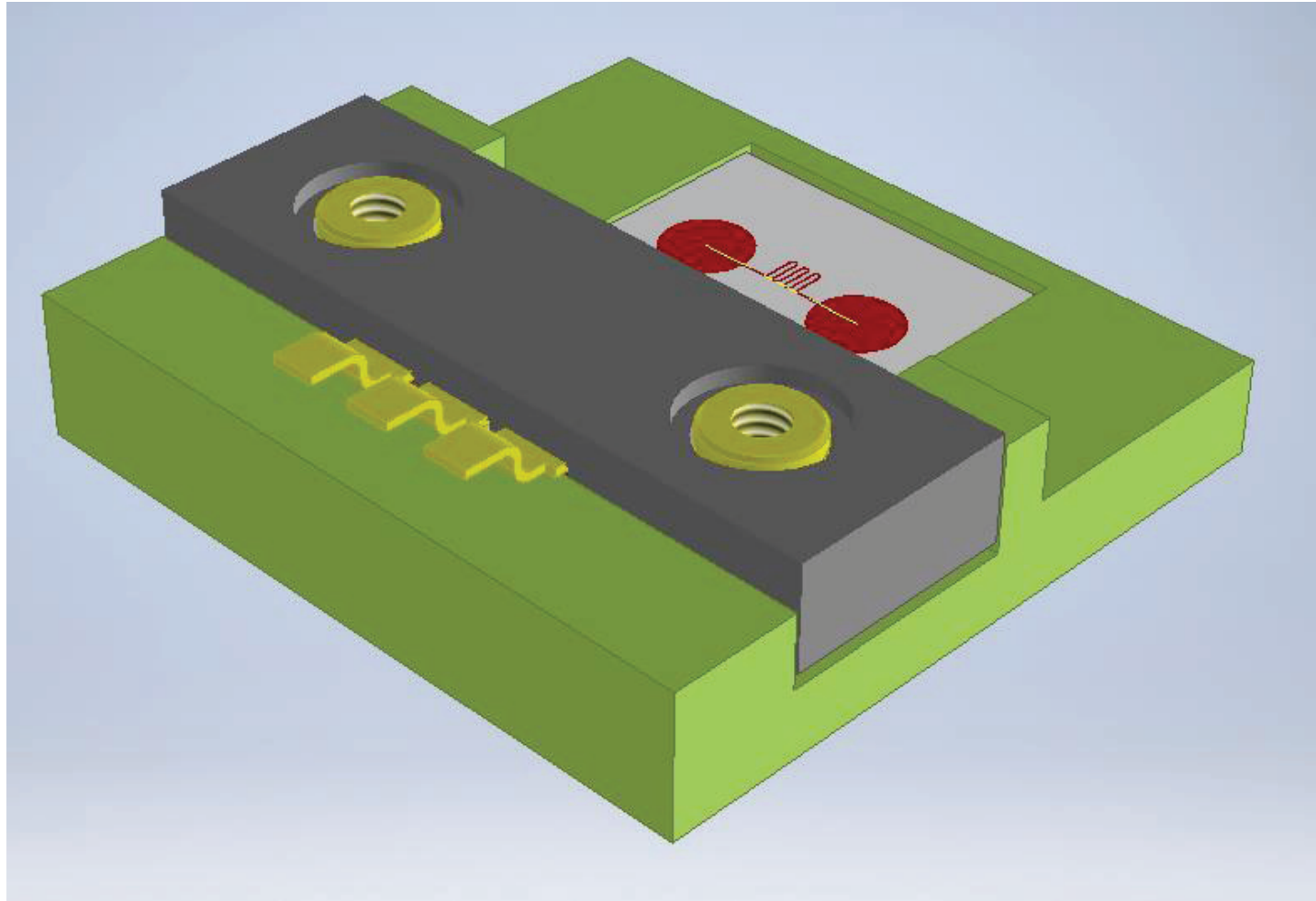
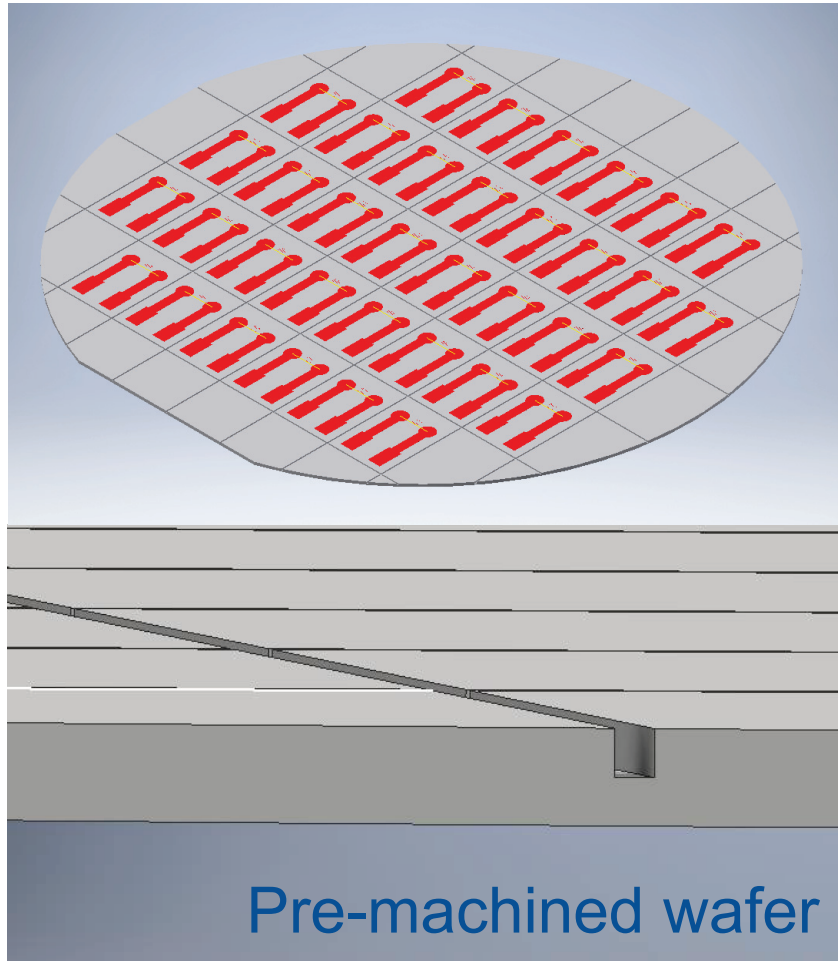
Stand-alone TES chips



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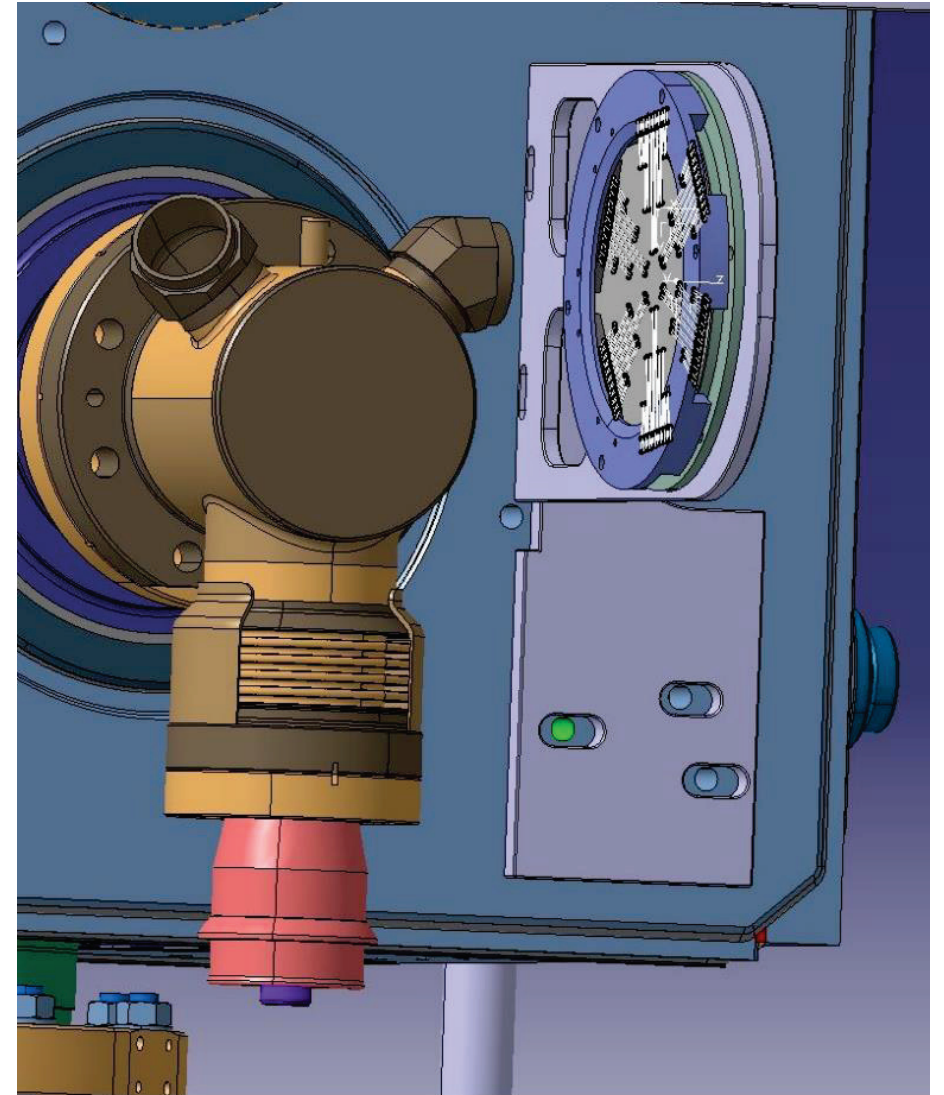
Towards the validation of TES as thermal mapping system

TES CRAB Cavities HOM - quench test

Very recently dressed CRAB cavity with HOMS tested at SM18

It was an opportunity to start commissioning TES as a quench localisation system at SM18

Test were done with OST's simultaneously, but no quench was detected at any HOMS

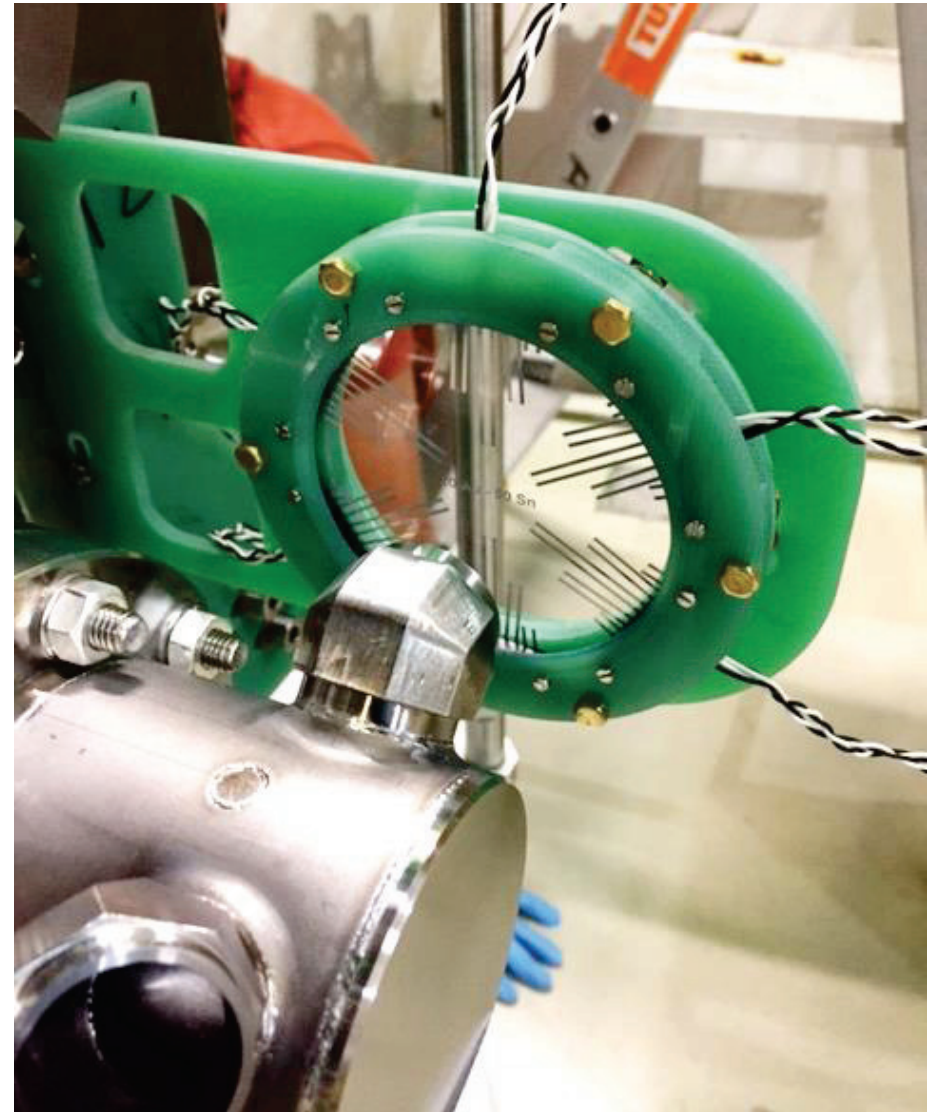


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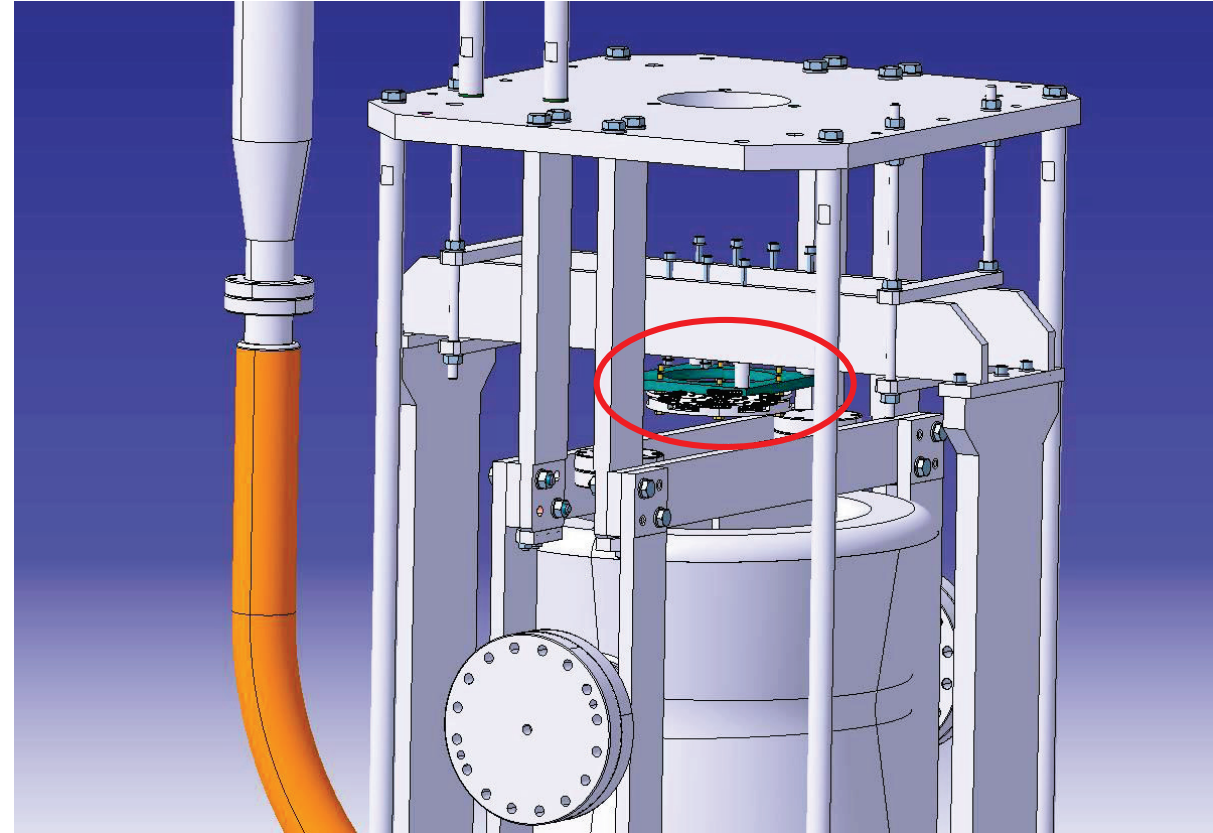


Bare cavity quench test with TES

Test the TES as a quench localisation system on a bare cavity

Current bare CRAB PoP cavity test is an opportunity

Alternative: Induce quench at known location on a cavity (heater or intentional surface defect) or simply test with a known bad-performing cavity

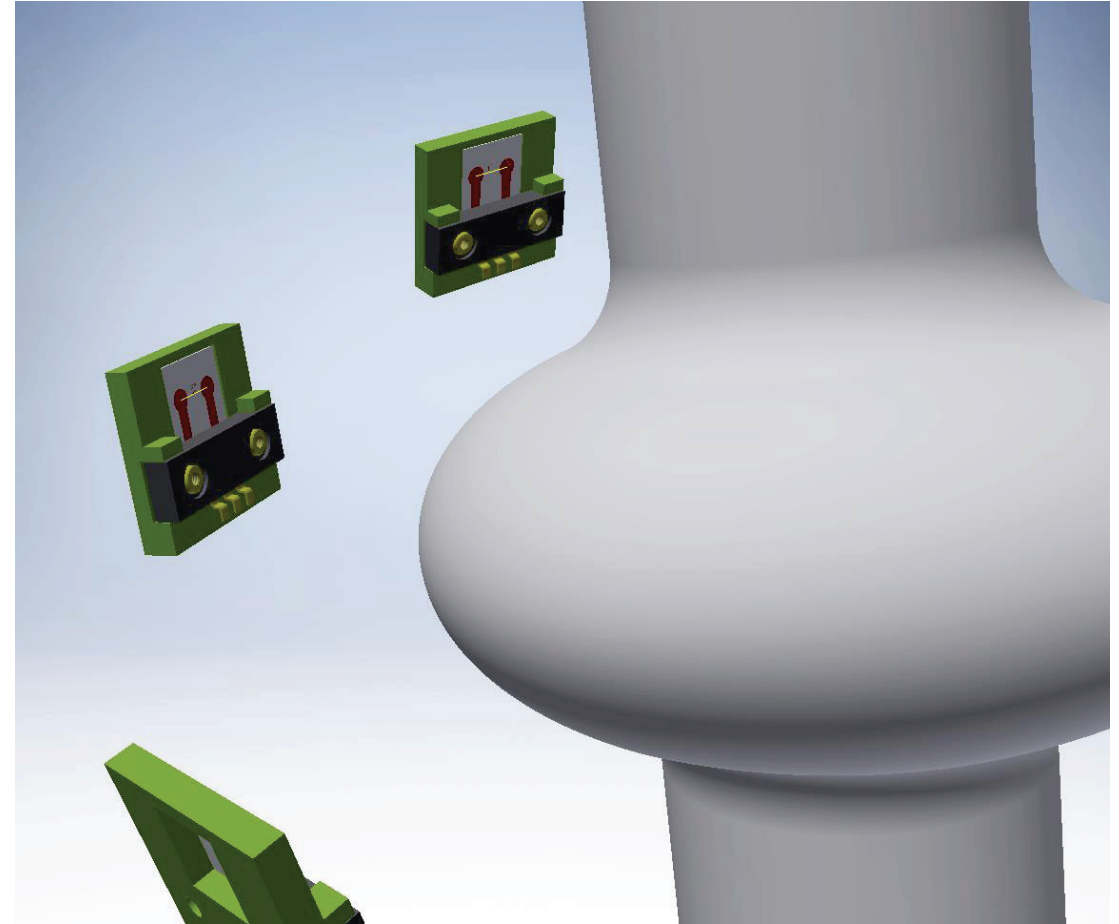


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Alternative: Induce quench at known location on a cavity (heater or intentional surface defect) or simply test with a known bad-performing cavity

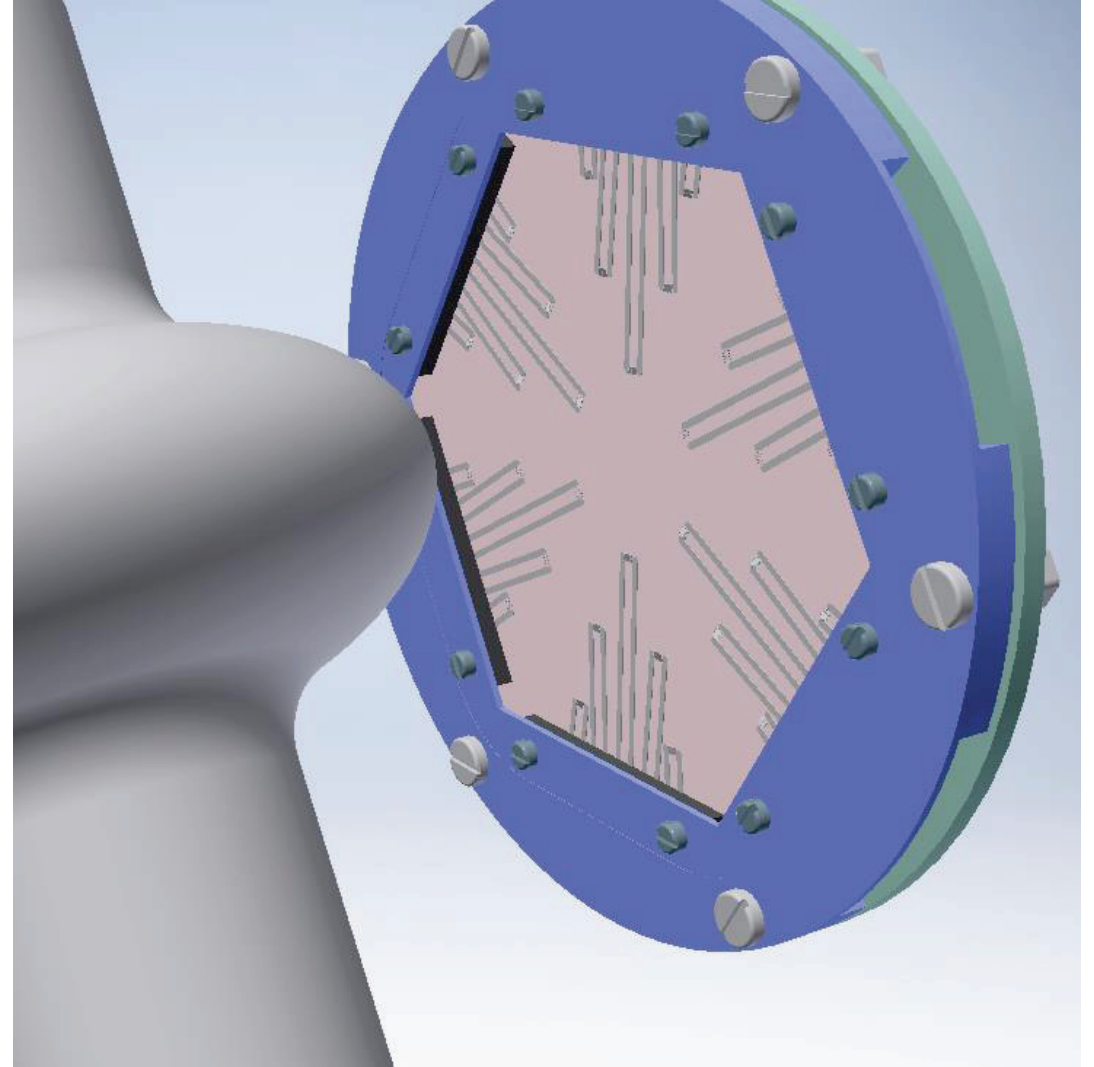


Bare cavity quench test with TES

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To summarize...

Conclusions on TES advances

TES as second sound detectors have been produced from Au-Sn thin films

The sensors were tested and satisfyingly detect second sound waves

Effects of composition, process flow parameters and adhesive layers have been/are being studied

A robust camera-like device has been designed, fabricated and incorporated to SM18 test facility

Next tests will allow to validate TES as a thermal mapping instrument and to compare their performance with that of OSTs

TES wafers as quench localization instruments are much more economic than a similar array of Cernox thermometers (when the technique is mastered and in relatively big production lots)

Acknowledgments

